

MC68HC05P3/D
Rev. 2

HCO5

MC68HC05P3
MC68HC705P3

TECHNICAL
DATA



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MC68HC05P3 MC68HC705P3

High-density complementary metal oxide semiconductor (HCMOS) microcontroller unit

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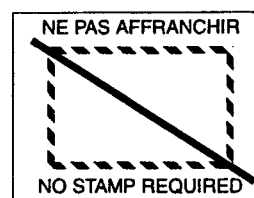
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1

INTRODUCTION

The MC68HC05P3 HCMOS microcomputer unit (MCU) is a powerful, low cost addition to the M68HC05 family. With its multipurpose core timer, a 16-bit programmable timer, 128 bytes of EEPROM and a keyboard interrupt facility, this general purpose MCU can be used in a variety of application areas. The MC68HC05P3 is available in 28-pin SOIC and 28-pin PDIP packages.

The MC68HC705P3 is an EPROM version of the MC68HC05P3 and is available in a one-time programmable 28-pin ceramic DIL package. All references to the MC68HC05P3 apply equally to the MC68HC705P3, unless otherwise noted. *References specific to the MC68HC705P3 are italicized in the text.*

Important: Information given for the MC68HC705P3 cannot be guaranteed. All values are design targets only and may change before the MC68HC705P3 is qualified.

1.1 Features

- Fully static design featuring the industry standard M68HC05 core
- On-chip oscillator
- 3072 bytes of user ROM plus 10 bytes of vectors; *3072 bytes of EPROM plus 10 bytes of vectors*
- 224 bytes of bootloader ROM plus 16 bytes of vectors
- 128 bytes of RAM
- 128 bytes of EEPROM
- Multipurpose core timer
- Real time interrupt (RTI)
- Computer operating properly (COP) watchdog timer
- 16-bit programmable timer
- 22 I/O lines
- Keyboard interrupt facility

- Power saving WAIT and low power STOP modes
- Available in 28-pin SOIC , 28-pin PDIP package and 28-pin ceramic DIL package

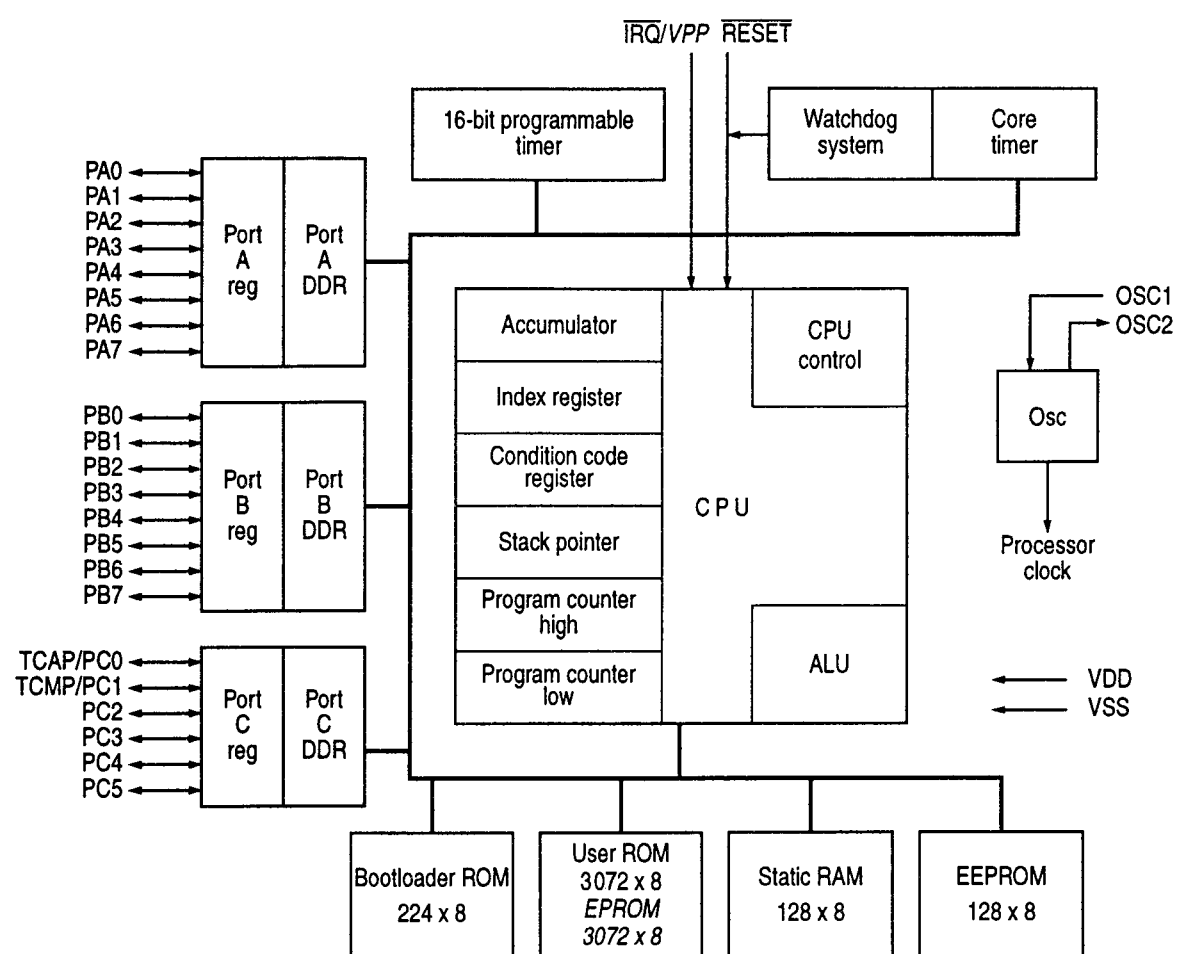


Figure 1-1 MC68HC05P3/MC68HC705P3 block diagram

1.2 Mask options for the MC68HC05P3

There are two mask options on the MC68HC05P3 which are programmed during manufacture and therefore must be specified on the order form: COP watchdog timer enable/disable and an option to make \overline{IRQ} either edge sensitive or edge-and-level sensitive.

1.3 Mask options for the MC68HC705P3

In the case of the MC68HC705P3, an option register replaces the mask options of the MC68HC05P3. Only two bits of this register are of interest to the user: OPTCOP and OPTIRQ. The remaining bits are reserved.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
\overline{IRQ} /COP status/control (OPT)	\$0F	0	1	0	0	1	0	OPTCOP	OPTIRQ	0100 1000

1.3.1 OPTCOP

OPTCOP enables or disables the COP. It is cleared by reset, thus enabling the COP. This bit can be written only once, so that the COP state can not be changed after the first write to this register. It is recommended that the user writes this bit as soon as possible after reset, in order to lock the state of the COP.

OPTCOP — Computer operating properly watchdog enable/disable

1 (set) — COP watchdog disabled.

0 (clear) — COP watchdog enabled.

1.3.2 OPTIRQ

Either an edge-and-level sensitive trigger, or an edge sensitive only trigger is selected by modifying bit 0 (OPTIRQ) of register \$0F. At reset this bit is cleared so that \overline{IRQ} is falling-edge sensitive only. The read/write bit must be set by software to get a falling-edge-and-low-level sensitive trigger.

OPTIRQ — Interrupt triggering sensitivity

1 (set) — \overline{IRQ} is falling-edge-and-low-level sensitive.

0 (clear) — \overline{IRQ} is falling-edge sensitive only.

Note: It is not advisable to change the value of OPTIRQ more than once, since this is not possible with the ROM version.
When changing the value of the OPTIRQ bit, the I-bit in the CCR should be set in order that all interrupts are disabled.


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2

MODES OF OPERATION AND PIN DESCRIPTIONS

The normal operating mode of the MC68HC05P3 is user (or single chip) mode. There is also a bootloader mode, primarily for factory test purposes. In addition to these modes, there are three low power modes which may be entered and exited at will from user mode: STOP, WAIT and data retention. *The MC68HC705P3 also has two modes of operation: user mode and EPROM bootloader mode. Table 2-1 shows the conditions required to enter the EPROM modes of operation on the rising edge of $\overline{\text{RESET}}$.*

Table 2-1 MC68HC705P3 operating mode entry conditions

RESET	IRQ/VPP	PC4	PC3	PC2	Mode	
	V_{SS} to V_{DD}	x	x	x	User	
	$2V_{DD}$	1	0	1	EPROM bootloader	Verify only
		1	1	0		Program 1 byte
		1	1	1		Program 4 bytes

x = don't care

2.1 User mode

This is the normal operating mode, in which the device functions as a self-contained microcomputer unit, with all on-board peripherals and I/O ports available to the user. All address and data activity occurs within the MCU.

Warning: *For the MC68HC705P3, all vectors are fetched from EPROM in user mode, therefore, the EPROM must be programmed (via the bootloader mode) before the device is powered up in user mode.*

2.2 EPROM bootloader mode for the MC68HC705P3

This mode is used for programming the on-board EPROM. In bootloader mode the operation of the device is the same as in user mode, except that the vectors are fetched from a reserved area of ROM at locations \$0FE0 to \$0FEF, instead of from the EPROM. The pin assignments are identical to those of user mode (see Figure 2-3). Because the addresses in the MC68HC705P3 and the external EPROM containing the user code are incremented independently, it is essential that the data layout in the 27256 EPROM conforms exactly to the MC68HC705P3 memory map.

The bootloader uses two external latches to address the memory device containing the code to be copied. Figure 2-1 shows a suggested EPROM programming circuit.

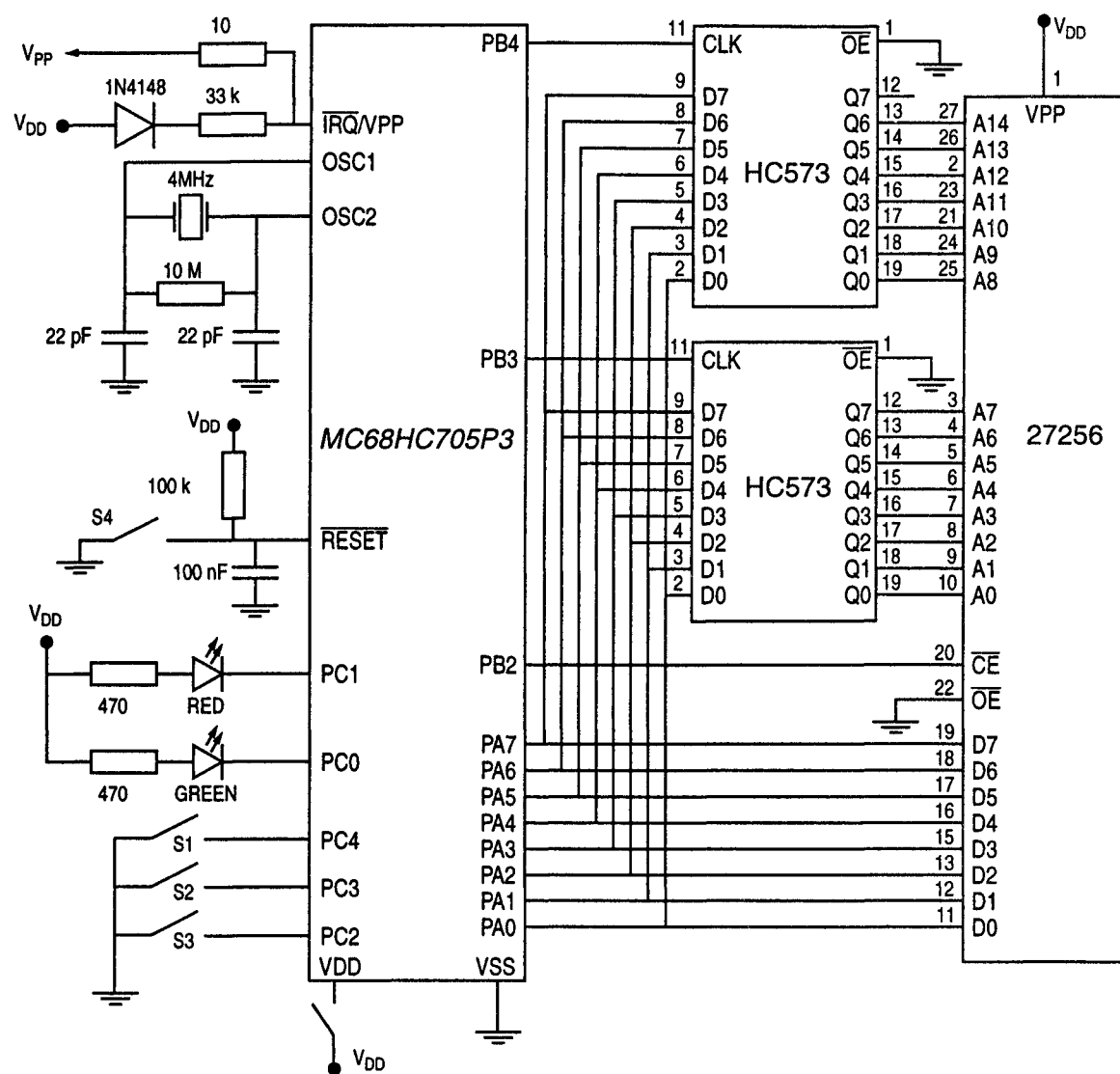


Figure 2-1 EPROM programming circuit

Warning: This mode must not be used in the user's application.

2.2.1 Bootloader functions

The bootloader code deals with the copying of user code from an external EPROM into the on-chip EPROM. The bootloader performs a programming pass and then does a verify pass.

Two pins, PC0 and PC1, are used to drive the PROG and VERF LED outputs. While the EPROM is being programmed, the PROG LED lights up; when programming is complete, the internal EPROM contents are compared to that of the external EPROM and, if they match exactly, the VERF LED lights up.

Note: The EPROM must be in the erased state before a program cycle. The erased state of the EPROM is \$00.

2.2.2 EPROM programming instructions

The following procedures should be carried out when programming the EPROM. In order to prevent damage to the device, V_{DD} should always be applied to the part before V_{PP} when powering up the device. Similarly, V_{PP} should be removed from the part before V_{DD} when switching the power off.

- 1) Turn off power to the circuit.
- 2) Install the MCU and the EPROM.
- 3) Select the bootloader function:
 Program 1 byte: Open S1 and S2 and close S3.
 Program 4 bytes: Open S1, S2 and S3.
 Verify only: Open S1 and S3 and close S2.
- 4) Close switch S4 to hold the MCU in reset.
- 5) Apply V_{DD} to the circuit.
- 6) Apply the EPROM programming voltage (V_{PP}) to the circuit.
- 7) Open switch S4 to take the MCU out of reset.
 During programming the PROG LED turns on and is switched off when the verification routine begins. If verification is successful, the VERF LED turns on. If the bootloader finds an error during verification, it puts the error address on the external address bus and stops running.
- 8) Close switch S4 to hold the MCU in reset.
- 9) Remove the V_{PP} voltage.
- 10) Remove the V_{DD} voltage.

Warning: EPROM programming must be carried out at room temperature.

2.3 Low power modes

2.3.1 STOP mode

The STOP instruction places the MCU in its lowest power consumption mode. In STOP mode, the internal oscillator is turned off, halting all internal processing, including timer (and COP watchdog timer) operation.

During STOP mode, the core timer interrupt flags (CTOF and RTIF) and interrupt enable bits (CTOFE and RTIE) in the CTCSR are cleared by internal hardware. The I-bit in the CCR is cleared to enable external interrupts. All other registers, the remaining bits in the CTCSR, and memory contents remain unaltered. All input/output lines remain unchanged. The processor can be brought out of STOP mode only by an external interrupt or a reset. See Figure 2-2.

2.3.2 WAIT mode

The WAIT instruction places the MCU in a low power consumption mode, though it consumes more power than in STOP mode. All CPU action is suspended, but the timers (core and 16-bit) remain active. An interrupt from either of the timers, if enabled, will cause the MCU to exit WAIT mode.

During WAIT mode, the I-bit in the CCR is cleared to enable interrupts. All other registers, memory and input/output lines remain in their previous state. The core timer may be enabled to allow a periodic exit from WAIT mode. See Figure 2-2.

2.3.3 Data retention mode

The contents of the RAM are retained at supply voltages as low as 2.0Vdc. This is called the data retention mode, in which data is maintained but the device is not guaranteed to operate.

For lowest power consumption in data retention mode the device should be put into STOP mode before reducing the supply voltage, to ensure that all the clocks are stopped. If the device is not in STOP mode then it is recommended that $\overline{\text{RESET}}$ be held low whilst the power supply is outwith the normal operating range, to ensure that processing is suspended in an orderly manner.

Recovery from data retention mode, after the power supply has been restored, is by an external interrupt, or by pulling the $\overline{\text{RESET}}$ line high.

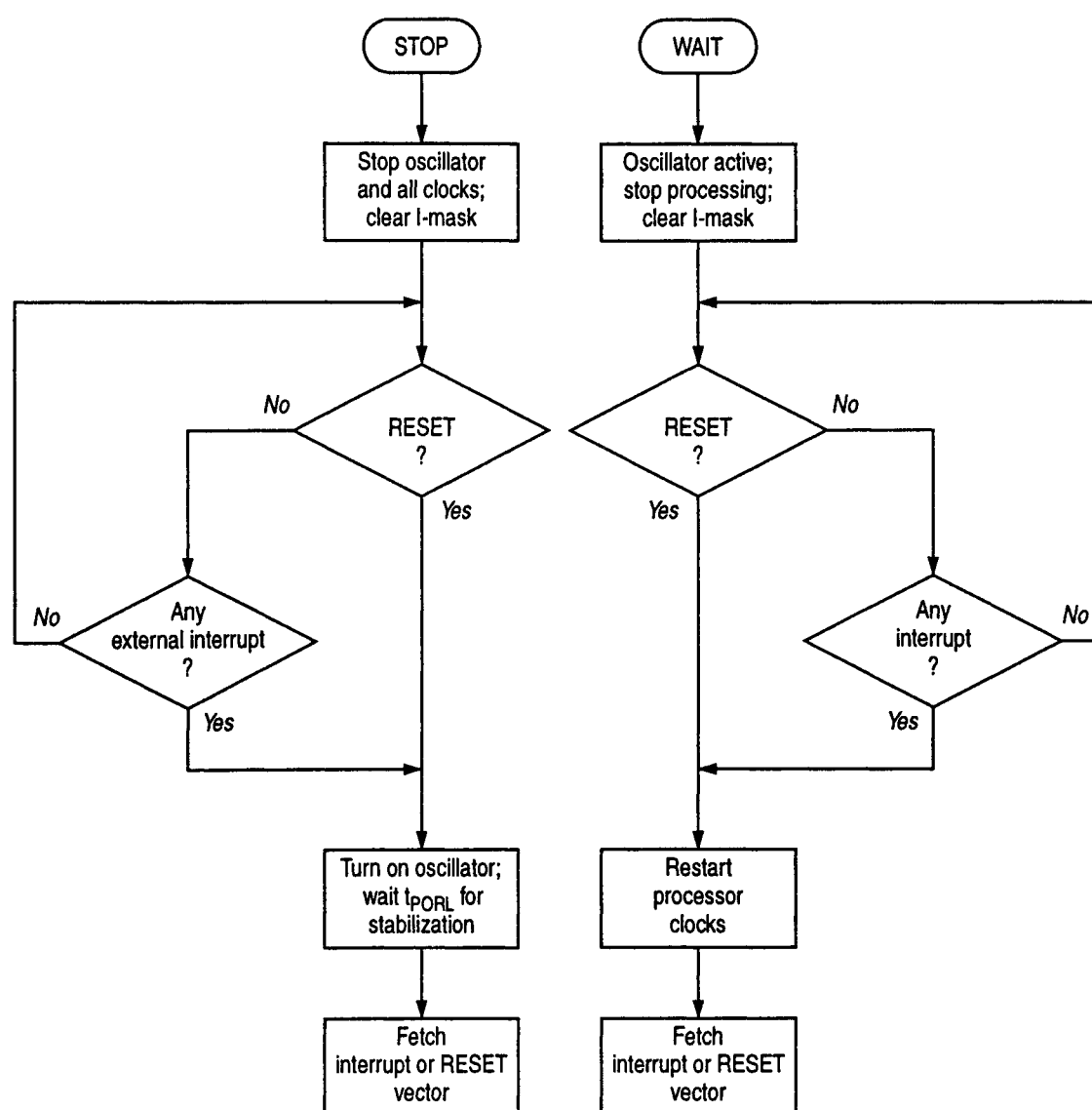


Figure 2-2 STOP and WAIT flowcharts

2.4 Pin descriptions

2.4.1 VDD and VSS

Power is supplied to the microcomputer via these two pins. VDD is the positive supply pin and VSS is the ground pin.

It is in the nature of CMOS designs that very fast signal transitions occur on the MCU pins. These short rise and fall times place very high short-duration current demands on the power supply. To prevent

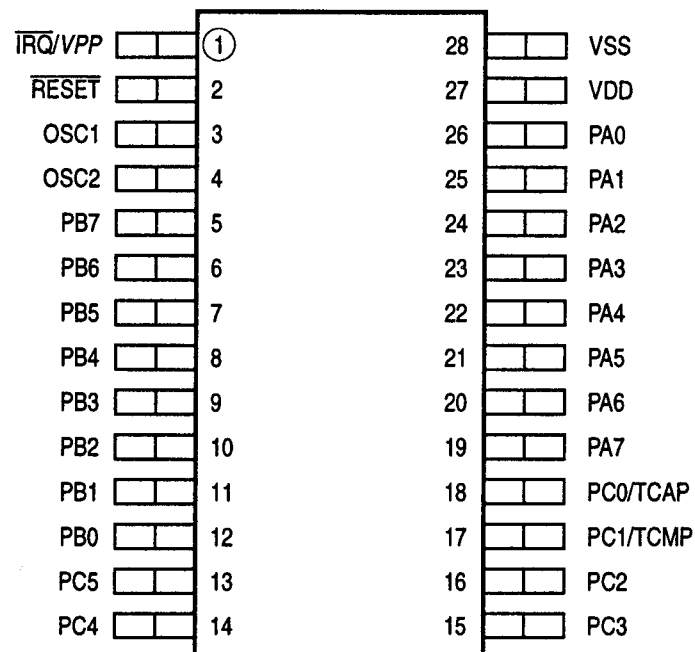


Figure 2-3 28-pin SOIC pinout

noise problems, special care must be taken to provide good power supply bypassing at the MCU. Bypass capacitors should have good high-frequency characteristics and be as close to the MCU as possible. Bypassing requirements vary, depending on how heavily the MCU pins are loaded.

2.4.2 RESET

This active low input pin is used to reset the MCU. Applying a logic zero to this pin forces the device to a known start-up state. An external RC-circuit can be connected to this pin to generate a power-on reset (POR) if required. In this case, the time constant must be great enough (at least 100ms) to allow the oscillator circuit to stabilize. This input has an internal Schmitt trigger to improve noise immunity.

2.4.3 IRQ / VPP

This is an input-only pin for external interrupt sources. A mask option selects interrupt triggering to be either falling-edge sensitive or falling-edge-and-low-level sensitive. *For the MC68HC705P3, this pin also serves as the input for the EPROM programming voltage (VPP).*

2.4.4 PA0 – PA7/PB0 – PB7

These 16 I/O lines comprise the two 8-bit ports A and B. The state of any pin is software programmable, and all the port pins are configured as inputs on reset.

2.4.5 PC0 – PC5

On reset this 6-bit I/O port behaves like ports A and B, all its pins being configured as inputs. However, by setting the keyboard interrupt enable bit in the KEY/TIM register, the pins will each be configured as inputs and will respond to a high-to-low input transition by generating a keyboard interrupt request. The interrupt vector is shared with that for \overline{IRQ} . A keyboard interrupt will bring the MCU out of STOP or WAIT mode.

In addition, Port C shares two pins with the 16-bit programmable timer, namely PC0/TCAP and PC1/TCMP. If the timer enable bit is set in the KEY/TIM register, then the TCAP and TCMP functions are active on their respective pins and the keyboard interrupt is disabled on them.

2.4.6 OSC1 and OSC2

These pins provide control input for an on-chip oscillator circuit. A crystal, ceramic resonator or external clock signal connected to these pins supplies the oscillator clock. The oscillator frequency (f_{OSC}) is divided by two to give the internal bus frequency (f_{OP}).

2.4.6.1 Crystal

The circuit shown in Figure 2-4(a) is recommended when using either a crystal or a ceramic resonator. Figure 2-4(d) provides the recommended capacitance and feedback resistance values. The internal oscillator is designed to interface with an AT-cut parallel-resonant quartz crystal resonator in the frequency range specified for f_{OSC} (see Section 9.4). Use of an external CMOS oscillator is recommended when crystals outside the specified ranges are to be used. The crystal and associated components should be mounted as close as possible to the input pins to minimize output distortion and start-up stabilization time. The manufacturer of the particular crystal being considered should be consulted for specific information.

2.4.6.2 Ceramic resonator

A ceramic resonator may be used instead of a crystal in cost sensitive applications. The circuit shown in Figure 2-4(a) is recommended when using either a crystal or a ceramic resonator. Figure 2-4(d) lists the recommended capacitance and feedback resistance values. The manufacturer of the particular ceramic resonator being considered should be consulted for specific information.

2.4.6.3 External clock

An external clock should be applied to the OSC1 input, with the OSC2 pin left unconnected, as shown in Figure 2-4(c). The t_{OXOV} specification (see Section 9.4) does not apply when using an external clock input. The equivalent specification of the external clock source should be used in lieu of t_{OXOV} .

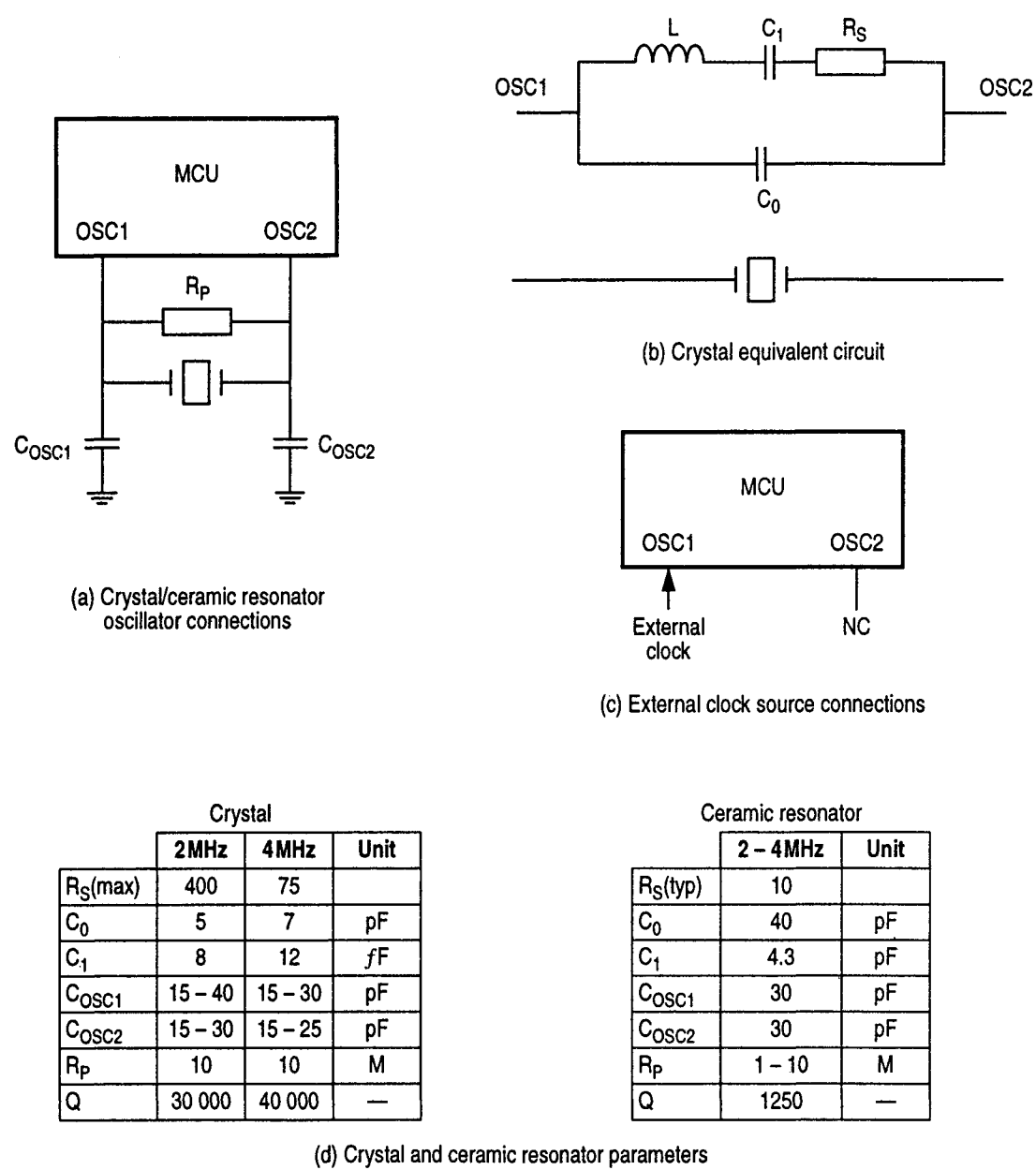


Figure 2-4 Oscillator connections

3

3

MEMORY AND REGISTERS

The MC68HC05P3 has a 4K byte memory map consisting of registers (for I/O, control and status), user RAM, user ROM or *EPROM*, EEPROM, bootloader ROM and reset and interrupt vectors as shown in Figure 3-1.

3.1 Registers

All the I/O, control and status registers of the MC68HC05P3 are contained within the first 32 byte block of the memory map, as detailed in Table 3-1.

3.2 RAM

The user RAM consists of 128 bytes of memory, from \$0080 to \$00FF. This is shared with a 64 byte stack area. The stack begins at \$00FF, and may extend down to \$00C0.

Note: Using the stack area for data storage or temporary work locations requires care to prevent the data from being overwritten due to stacking from an interrupt or subroutine call.

3.3 ROM (MC68HC05P3 only)

The user ROM occupies 3072 bytes of memory, from \$0300 to \$0EFF. In addition, there are ten bytes of user vectors, from \$0FF6 to \$0FFF.

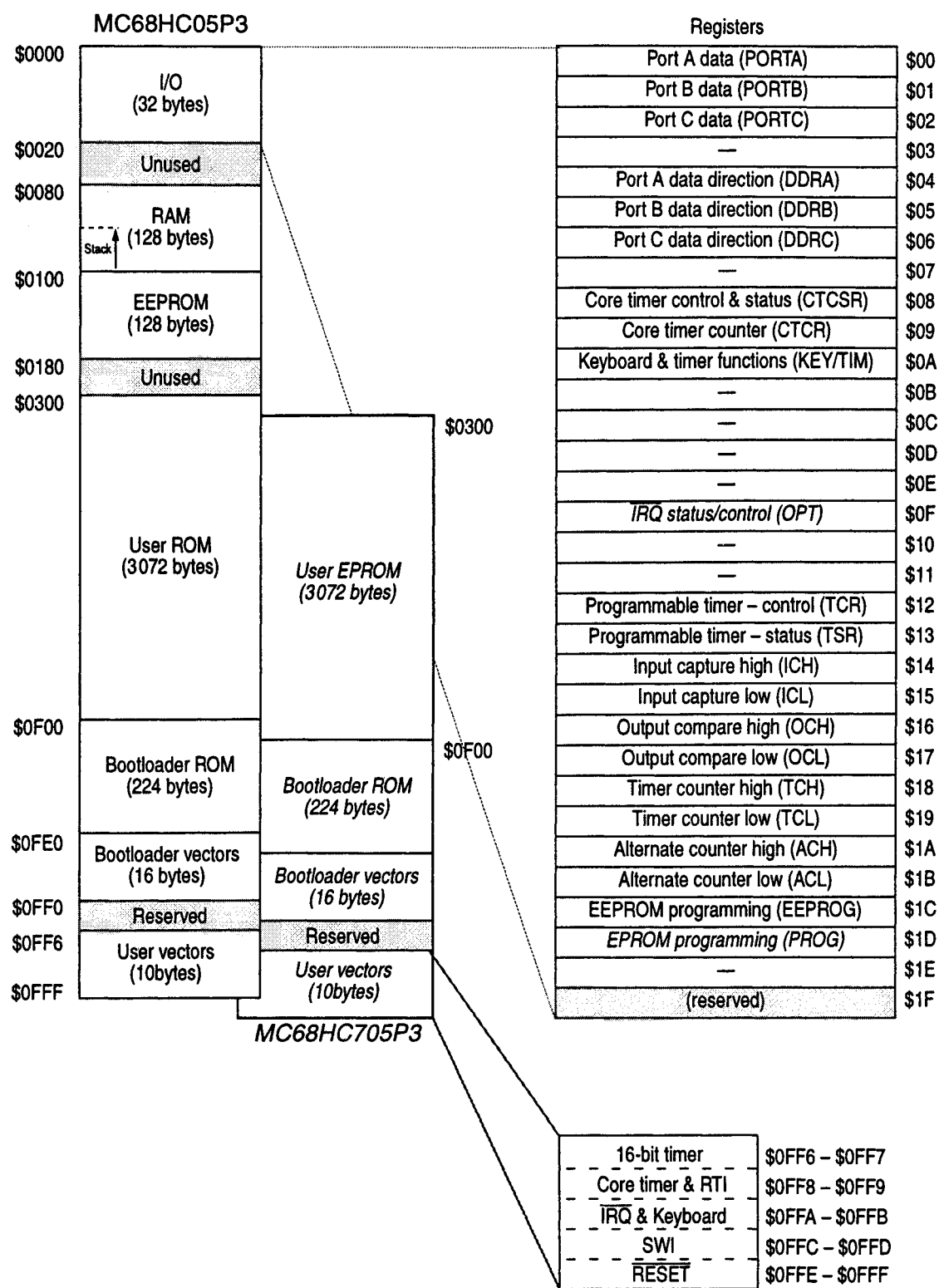


Figure 3-1 Memory map of the MC68HC05P3 and MC68HC705P3

Table 3-1 Register outline

Register Name	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Port A data (PORTA)	\$0000	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0	undefined
Port B data (PORTB)	\$0001	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0	undefined
Port C data (PORTC)	\$0002			PC5	PC4	PC3	PC2	PC1	PC0	undefined
Port A data direction (DDRA)	\$0004									0000 0000
Port B data direction (DDRB)	\$0005									0000 0000
Port C data direction (DDRC)	\$0006									0000 0000
Core timer control/status (CTCSR)	\$0008	CTOF	RTIF	CTOFE	RTIE	0	0	RT1	RT0	0000 0011
Core timer counter (CTCR)	\$0009									0000 0000
Keyboard/timer (KEY/TIM)	\$000A						TIMEN	KSF	KIE	uuuu u000
IRQ status/control (OPT)	\$000F	0	1	0	0	1	0	OPTCOP	OPTIRQ	0100 1000
Timer control (TCR)	\$0012	ICIE	OCIE	TOIE				IEDG	OLVL	000u uu00
Timer status (TSR)	\$0013	ICF	OCF	TOF						uuuu uuuu
Input capture high (ICH)	\$0014	(bit 15)							(bit 8)	undefined
Input capture low (ICL)	\$0015									undefined
Output compare high (OCH)	\$0016	(bit 15)							(bit 8)	undefined
Output compare low (OCL)	\$0017									undefined
Timer counter high (TCH)	\$0018	(bit 15)							(bit 8)	\$FF
Timer counter low (TCL)	\$0019									\$FC
Alternate counter high (ACH)	\$001A	(bit 15)							(bit 8)	\$FF
Alternate counter low (ACL)	\$001B									\$FC
EEPROM programming (EPROG)	\$001C	0	CPEN	0	ER1	ER0	LATCH	EERC	EEPGM	0000 0000
EPROM programming (PROG)	\$001D	0	0	0	0	0	ELATCH	0	EPGM	0000 0000
(reserved)	\$001F	0	0	0	0	0	0	0	0	0000 0000

u = undefined

3.4 Bootloader ROM

The MC68HC05P3 has 224 bytes of bootloader ROM plus 16 bytes of bootloader vectors, from \$0F00 to \$0FEF. These are included primarily for factory test purposes.

The MC68HC705P3 also has 224 bytes of bootloader ROM, ranging from \$0F00 to \$0FDF, and bootloader vectors from \$0FE0 to \$0FEF. This program contains code to program the EPROM by copying from a 27256 EPROM master device.

Note: The bootloader ROM is not accessible if the ELATCH bit in the EPROM programming register (\$1D) is set.

3.5 EPROM (MC68HC705P3 only)

The MC68HC705P3 has 3072 bytes of EPROM located from \$0300 to \$0EFF, plus 10 bytes of user vectors from \$0FF6 to \$0FFF. Four bytes of EPROM can be programmed simultaneously by correctly manipulating the bits in the EPROM programming register.

3.5.1 EPROM programming register (PROG)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
EPROM programming (PROG)	\$001D	0	0	0	0	0	ELATCH	0	EPGM	0000 0000

EPGM — EPROM program control

1 (set) — Programming power connected to the EPROM array.

0 (clear) — Programming power disconnected from the EPROM array.

ELATCH and EPGM cannot be set on the same write operation. EPGM can only be set if ELATCH is set. EPGM is automatically cleared when ELATCH is cleared.

ELATCH — EPROM latch control

1 (set) — EPROM address and data buses configured for programming.

0 (clear) — EPROM address and data buses configured for normal reads

ELATCH causes address and data buses to be latched when a write to EPROM is carried out. The EPROM cannot be read if ELATCH = 1. This bit should not be set unless a programming voltage is applied to the VPP pin.

The following steps should be taken to program a byte of EPROM:

- 1) *Apply the programming voltage V_{PP} to the \overline{TRQ}/VPP pin.*
- 2) *Set the ELATCH bit.*
- 3) *Write to the EPROM address.*
- 4) *Set the EPGM bit for a time t_{EPGM} to apply the programming voltage.*
- 5) *Clear the ELATCH bit.*

If the address bytes A15–A2 do not change, i.e. all bytes are located within the same four byte address block, then multibyte programming is permitted. The multibyte programming facility allows four bytes of data to be written to the desired addresses after the ELATCH bit has been set (see Table 2-1 for multibyte programming entry conditions).

Note: *The erased state of the EPROM is \$00.*

3.6 EEPROM

128 bytes of user EEPROM reside at addresses \$0100 to \$017F.

Programming or erasing the EEPROM can be done by the user on a single byte basis; erasing may also be performed on a block or bulk basis. All programming or erasing is accomplished by manipulating the programming register (EEPROG), located at address \$001C.

Note: The erased state of an EEPROM byte is '\$FF'. This means that a write forces zeros to the bits specified, whilst bits defined as ones are unchanged by a write operation.

3.6.1 EEPROM programming register

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
EEPROM programming (EPROG)	\$001C	0	CPEN	0	ER1	ER0	LATCH	EERC	EEPGM	0000 0000

CPEN — Charge pump enable

- 1 (set) – Charge pump enabled.
- 0 (clear) – Charge pump disabled.

When set, CPEN enables the charge pump which produces the internal programming voltage. This bit should be set at the same time as the LATCH bit. The programming voltage will not be available until EEGPM is set. The charge pump should be disabled when not in use. CPEN is readable and writable and is cleared by reset.

ER1, ER0 — Erase select bits

ER1 and ER0 are used to select either single byte programming or one of three erase modes: byte, block, or bulk. Table 3-2 shows the mode selected for each bit configuration. These bits are readable and writable and are cleared by reset.

Table 3-2 Erase modes

ER1	ER0	Mode
0	0	Program
0	1	Byte erase
1	0	Block erase
1	1	Bulk erase

- In byte erase mode, only the selected byte is erased.
- In block erase mode, a 32-byte block of EEPROM is erased. The EEPROM memory space is divided into four 32-byte blocks (\$0100 – \$011F, \$0120 – \$013F, \$0140 – \$015F and \$0160 – \$017F) and performing a block erase on any address within a block will erase the entire block.
- In bulk erase mode, the entire 128 bytes of EEPROM are erased.

LATCH — EEPROM latch bit

- 1 (set) – EEPROM address and data buses are configured for programming.
- 0 (clear) – EEPROM address and data buses are configured for normal operation.

When set, the LATCH bit configures the EEPROM address and data buses for programming. In addition, writes to the EEPROM array cause the address and data buses to be latched. This bit is readable and writable, but reads from the EEPROM array are inhibited if the LATCH bit is set and a write to the EEPROM space has taken place. When this bit is clear, address and data buses are configured for normal operation. Reset clears this bit.

EERC — EEPROM RC oscillator control

- 1 (set) – Use internal RC oscillator for EEPROM.
- 0 (clear) – Use CPU clock for EEPROM.

When this bit is set, the EEPROM memory array uses the internal RC oscillator instead of the CPU clock. After setting the EERC bit, the user should wait a time t_{RCON} to allow the RC oscillator to stabilize. This bit is readable and writable and should be set by the user when the internal bus frequency falls below 1.5MHz. Reset clears this bit.

EEPGM — EEPROM programming power enable

- 1 (set) – Programming power connected to the EEPROM array.
- 0 (clear) – Programming power switched off.

EEPGM must be set to enable the EEGPM function. When set, EEGPM turns on the charge pump and enables the programming (or erasing) power to the EEPROM array. When clear, this power is switched off. This will enable pulsing of the programming voltage to be controlled internally. This bit can be read at any time, but can only be written to if LATCH = 1, i.e. if LATCH is not set, then EEGPM cannot be set. Reset clears this bit.

3.6.2 Programming and erasing procedures

To program a byte of EEPROM, set LATCH = CPEN = 1, set ER1 = ER0 = 0, write data to the desired address and then set EEPGM for a time t_{EPGM} .

3

There are three possibilities for erasing data from the EEPROM array, depending on how much data is affected.

- To erase a byte of EEPROM, set LATCH = CPEN = 1, set ER1 = 0 and ER0 = 1, write data to the desired address and then set EEPGM for a time t_{EBYTE} .
- To erase a block of EEPROM, set LATCH = CPEN = 1, set ER1 = 1 and ER0 = 0, write data to any address in the block and then set EEPGM for a time t_{EBLOCK} .
- To bulk erase the EEPROM, set LATCH = CPEN = 1, set ER1 = ER0 = 1, write data to any address in the array and then set EEPGM for a time t_{EBULK} .

To terminate the programming or erase sequence, clear EEPGM, wait for a time t_{FPV} to allow the programming voltage to fall, and then clear LATCH and CPEN to release the buses. Following each erase or programming sequence, clear all programming control bits.

3.6.3 Sample EEPROM programming sequence

The following program is an example of the EEPROM programming sequence, using the timer to implement the required delay and assuming a 1 MHz bus frequency.

```

TCSR EQU $0008      TIMER CONTROL AND STATUS REGISTER
TCNT EQU $0009      TIMER COUNTER REGISTER
TOF EQU 7           TOF BIT OF TCSR
PROG EQU $001C      EEPROM PROGRAM REGISTER
CPEN EQU 6          CHARGE PUMP ENABLE BIT
ER1 EQU 4           ERASE SELECT BIT 1
ER0 EQU 3           ERASE SELECT BIT 0
LATCH EQU 2         LATCH BIT
EERC EQU 1          RC/OSC SELECTOR BIT
EEPGM EQU 0         EEPROM PROGRAM BIT
EESTARTEQU $0100    START ADDRESS OF EEPROM
SUMPIN EQU $FF      DUMMY DATA

```

```

ORG $0680

```

```

START EQU *
      BSET EERC, PROG    SELECT RC OSCILLATOR
      BSR  DELAY         RC OSCILLATOR STABILIZATION
      BSET CPEN, PROG    TURN ON CHARGE PUMP
      BSET LATCH, PROG   ENABLE LATCH BIT
      BCLR ER1, PROG     SELECT PROGRAM (NOT ERASE)
      BCLR ER0, PROG     SELECT PROGRAM (NOT ERASE)

      LDA #SUMPIN        GET DATA
      STA EESTART
      BSET EEPGM, PROG    ENABLE PROGRAMMING POWER
      JSR DELAY           WAIT FOR PROGRAMMING TIME
      BCLR EEPGM, PROG    CLEAR EEPGM

      JSR DELAY           WAIT FOR PROG VOLTAGE TO FALL
      BCLR LATCH, PROG    CLEAR LATCH
      BCLR CPEN, PROG     DISABLE CHARGE PUMP
      CMP  EESTART        VERIFY
      BNE OUT1
      CLC                 CLEAR CARRY BIT IF NO ERROR

```

```

OUT RTS

```

```

OUT1 SEC          FLAG AN ERROR
      RTS

```

*THIS ROUTINE GIVES A 15MS (+/-1MS) DELAY AT 1 MHZ BUS. THE SAME DELAY
 * ROUTINE IS USED IN THIS EXAMPLE FOR SIMPLICITY, USING THE LONGEST DELAY
 * TIME. USERS WILL WANT TO WRITE SHORTER DELAY ROUTINES FOR APPLICATIONS
 *IN WHICH SPEED IS IMPORTANT.

```

DELAY EQU *
      LDX #15          COUNT OF 15
TIMLP BCLR TOF, TCSR    CLEAR TOF
      BRCLR TOF, TCSR, * WAIT FOR TOF FLAG
      DECX
      BNE TIMLP        COUNT DOWN TO 0
      RTS

```

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4

PARALLEL INPUT/OUTPUT PORTS

4

The MC68HC05P3 has a total of 22 I/O lines, arranged as two 8-bit ports and one 6-bit port. The I/O lines are individually programmable as either input or output, under the software control of the data direction registers. The 6-bit Port C can also be configured to respond to keyboard interrupts.

To avoid glitches on the output pins, data should be written to the I/O port data register before writing ones to the corresponding data direction register bits to set the pins in output mode.

4.1 Input/output programming

The bidirectional port lines may be programmed as inputs or outputs under software control. The direction of each pin is determined by the state of the corresponding bit in the port data direction register (DDR). Each I/O port has an associated DDR. Any I/O port pin is configured as an output if its corresponding DDR bit is set to a logic one. A pin is configured as an input if its corresponding DDR bit is cleared.

At power-on or reset, all DDRs are cleared, thus configuring all port pins as inputs. The data direction registers can be written to or read by the MCU. During the programmed output state, a read of the data register actually reads the value of the output data latch and not the I/O pin. The operation of the standard port hardware is shown schematically in Figure 4-1.

This is further summarized in Table 4-1, which shows the effect of reading from, or writing to an I/O pin in various circumstances. Note that the read/write signal shown is internal and not available to the user.

4.2 Ports A and B

These ports are standard M68HC05 bidirectional I/O ports, each comprising a data register and a data direction register.

Reset does not affect the state of the data register, but clears the data direction register, thereby returning all port pins to input mode. Writing a '1' to any DDR bit sets the corresponding port pin to output mode.

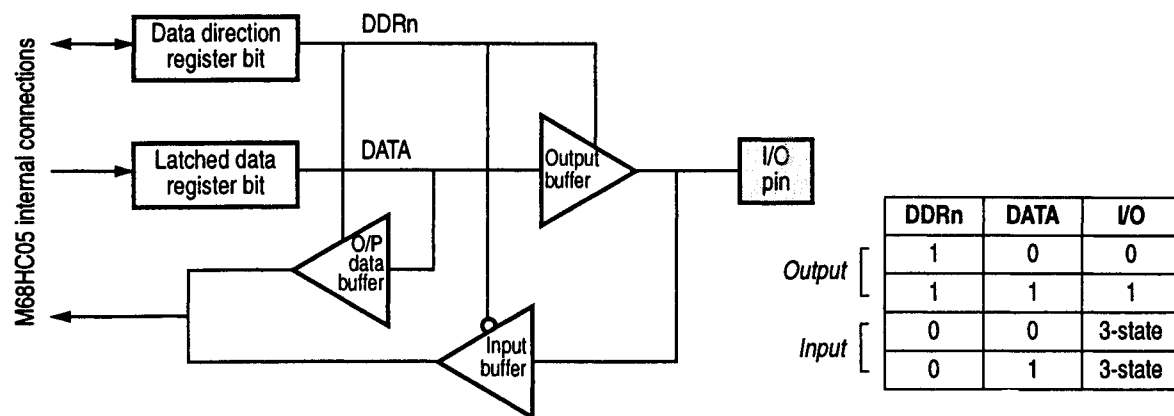


Figure 4-1 Standard I/O port structure

Table 4-1 I/O pin states

R/W	DDRn	Action of MCU write to/read of data bit
0	0	The I/O pin is in input mode. Data is written into the output data latch.
0	1	Data is written into the output data latch, and output to the I/O pin.
1	0	The state of the I/O pin is read.
1	1	The I/O pin is in output mode. The output data latch is read.

4.3 Port C

In addition to the standard port functions, this 6-bit port has a programmable keyboard interrupt feature, with internal pull-up resistors. (This pull-up is present whenever the port is in input mode.) On reset, this port is configured as a standard I/O port, comprising a data register and a data direction register.

Reset does not affect the state of the data register, but clears the data direction register, thereby returning all port pins to input mode. Writing a '1' to any DDR bit sets the corresponding port pin to output mode.

Provided that the interrupt mask bit of the condition code register is cleared, the keyboard interrupt facility is enabled by setting the keyboard interrupt bit (KIE) in the KEY/TIM register.

Setting KIE will force each of the I/O lines of the port to be an input, with an internal pull-up resistor (R_{PORTC}). Typical R_{PORTC} are given in Table 9-3 and Table 9-4. The structure of the port pins is shown diagrammatically in Figure 4-2. When a high-to-low transition is detected on any of this port's pins then a keyboard interrupt request is generated and the keyboard status flag (KSF) is set. The address of the interrupt service routine is specified by the contents of memory locations \$0FFA and \$0FFB. Since this interrupt vector is shared with the IRQ external interrupt function the interrupt service routine should check KSF to determine the interrupt source. KSF should be cleared by software in the interrupt service routine. Care must be taken to allow adequate time for switch debounce before clearing the flag.

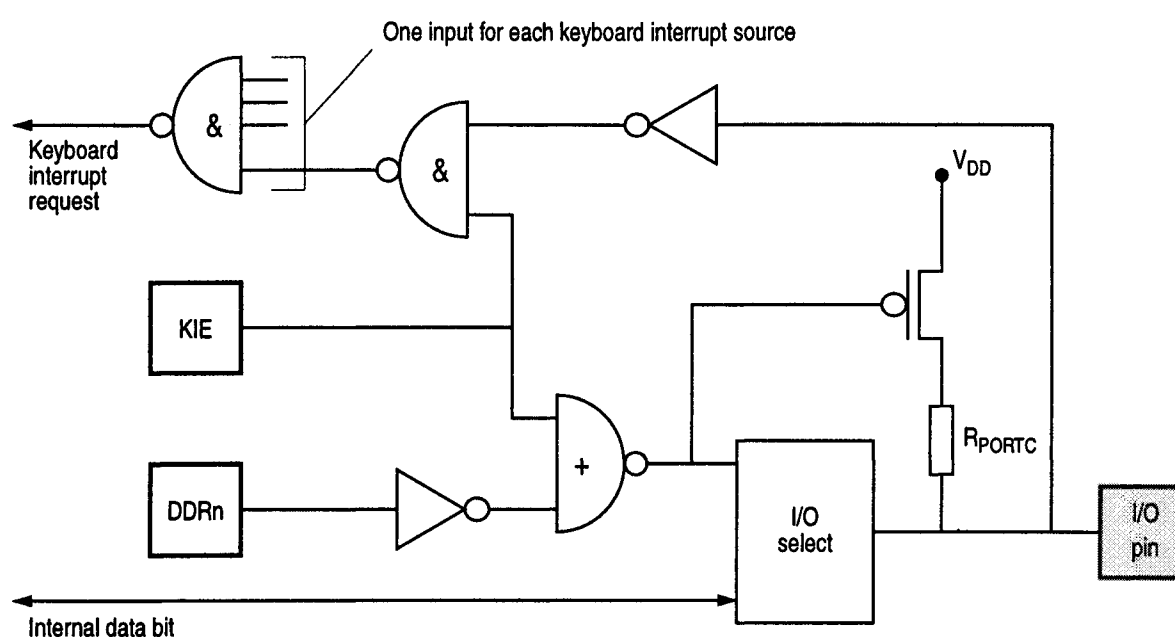


Figure 4-2 Structure of port with keyboard interrupt

A keyboard interrupt will force the MCU out of STOP or WAIT mode.

In addition to their I/O functions two pins of this port can also be configured to support the TCAP and TCMP timer functions instead. If the TIMEN bit in the KEY/TIM register is set then the PC0 and PC1 pins function as TCAP and TCMP respectively. In this case the keyboard interrupt is disabled on these two pins.

On reset, all bits in the KEY/TIM register are cleared, hence disabling both keyboard interrupt and timer functions.

4.4 Port registers

The following sections explain in detail the individual bits in the data and control registers associated with the ports.

4.4.1 Port data registers (Port A, Port B and Port C)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Port A data (PORTA)	\$0000	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0	undefined
Port B data (PORTB)	\$0001	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0	undefined
Port C data (PORTC)	\$0002			PC5	PC4	PC3	PC2	PC1	PC0	undefined

Each bit can be configured as input or output via the corresponding data direction bit in the port data direction register (DDRx).

Reset does not affect the state of the port data registers.

4.4.2 Data direction registers (DDRA, DDRB and DDRC)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Port A data direction (DDRA)	\$0004									0000 0000
Port B data direction (DDRB)	\$0005									0000 0000
Port C data direction (DDRC)	\$0006									0000 0000

Writing a '1' to any bit configures the corresponding port pin as an output; conversely, writing any bit to '0' configures the corresponding port pin as an input.

Reset clears these registers, thus configuring all port pins as inputs.

4.4.3 Keyboard interrupt register (KEY/TIM)

This register contains three bits, two of which are used to control the keyboard interrupt facility, the other the timer function.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Keyboard/timer (KEY/TIM)	\$000A						TIMEN	KSF	KIE	---- - 000

4.4.3.1 TIMEN — Timer enable

- 1 (set) — 16-bit timer enabled.
- 0 (clear) — 16-bit timer disabled.

For further details on this bit, see Section 6.1.

Note: If TIMEN is set, PC0 and PC1 are dedicated to the timer and lose their port functions.

4

4.4.3.2 KSF — Keyboard interrupt status flag

- 1 (set) — A valid transition has occurred on one of the port pins.
- 0 (clear) — No valid transition has occurred on any of the port pins.

This bit is set when a high-to-low transition is detected on any of the port C pins; a keyboard interrupt request will be generated, if keyboard interrupts are enabled (only if KIE is set). The KSF flag is cleared by writing to the bit.

4.4.3.3 KIE — keyboard interrupt enable

- 1 (set) — Keyboard interrupt enabled.
- 0 (clear) — Keyboard interrupt disabled.

An interrupt can only be generated if KIE and KSF are both set and the I-bit in the CCR is clear.

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5

CORE TIMER

The MC68HC05P3 has a 15-stage ripple counter called the core timer (CTIMER). Features of this timer are: timer overflow, power-on reset (POR), real time interrupt (RTI) with four selectable interrupt rates and a computer operating properly (COP) watchdog timer.

5

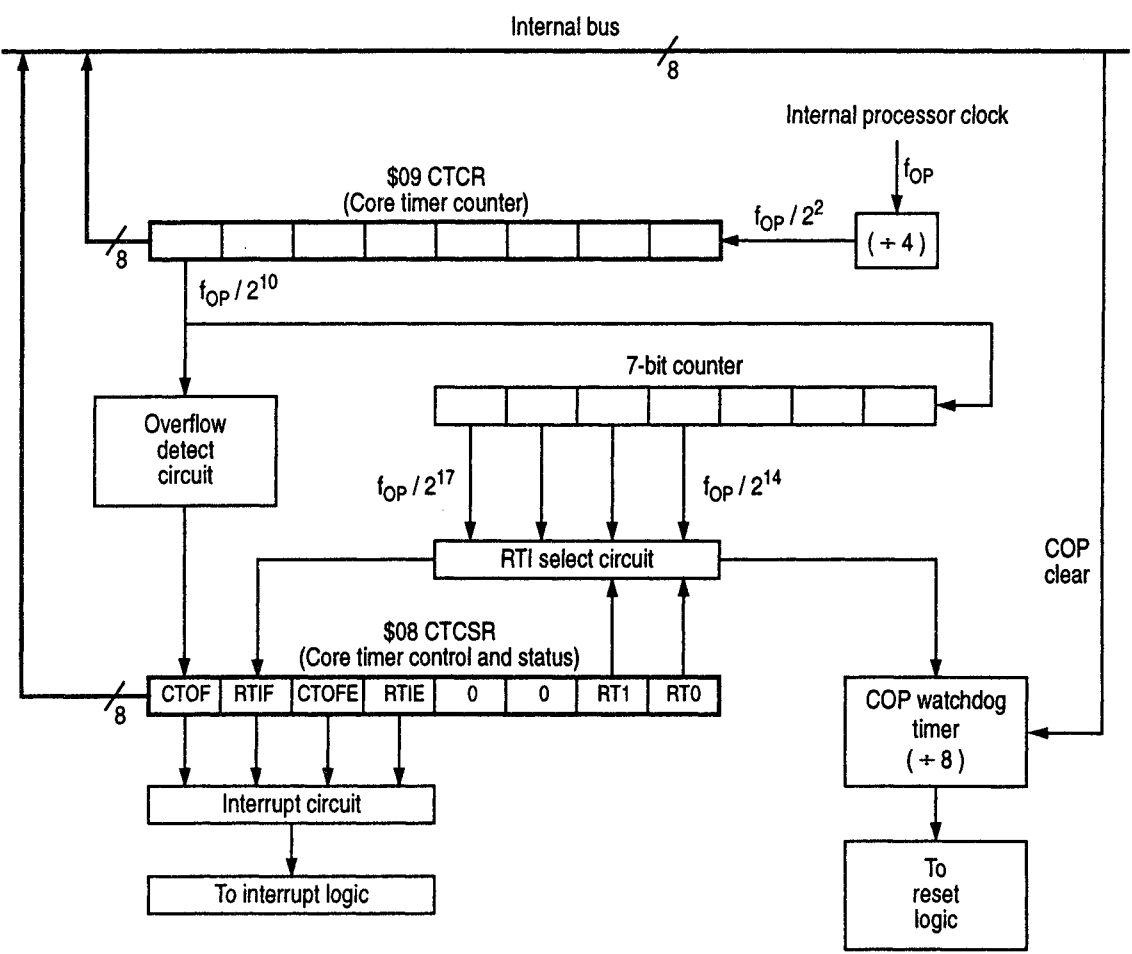


Figure 5-1 Core timer block diagram

As shown in Figure 5-1, the timer is driven by the internal bus clock divided by four with a fixed prescaler. This signal drives an 8-bit ripple counter. The value of this 8-bit ripple counter can be read by the CPU at any time, by accessing the CTIMER counter register (CTCR) at address \$09. A timer overflow function is implemented on the last stage of this counter, giving a possible interrupt at the rate of $f_{OP}/1024$. (The POR signal (t_{PORL}) is also derived from this register, at $f_{OP}/4064$.) The counter register circuit is followed by four more stages, with the resulting clock ($f_{OP}/16384$) driving the real time interrupt circuit. The RTI circuit consists of three divider stages with a 1-of-4 selector. The output of the RTI circuit is further divided by 8 to drive the COP watchdog timer circuit. The RTI rate selector bits, and the RTI and CTIMER overflow enable bits and flags, are located in the CTIMER control and status register (CTCSR) at location \$08.

CTOF (core timer overflow flag) is a clearable, read-only status bit and is set when the 8-bit ripple counter rolls over from \$FF to \$00. A CPU interrupt request will be generated if CTOFE is set. Clearing the CTOF is done by writing a '0' to it. Writing a '1' to CTOF has no effect on the bit's value. Reset clears CTOF.

When CTOFE (core timer overflow enable) is set, a CPU interrupt request is generated when the CTOF bit is set. Reset clears CTOFE.

The core timer counter register (CTCR) is a read-only register that contains the current value of the 8-bit ripple counter at the beginning of the timer chain. This counter is clocked at $f_{OP}/4$ and can be used for various functions including a software input capture. Extended time periods can be attained using the CTIMER overflow function to increment a temporary RAM storage location thereby simulating a 16-bit (or more) counter.

The power-on cycle clears the entire counter chain and begins clocking the counter. After t_{PORL} cycles, the power-on reset circuit is released, which again clears the counter chain and allows the device to come out of reset. At this point, if \overline{RESET} is not asserted, the timer will start counting up from zero and normal device operation will begin. When \overline{RESET} is asserted at any time during operation (other than POR), the counter chain will be cleared.

5.1 Real time interrupts (RTI)

The real time interrupt circuit consists of a three stage divider and a 1-of-4 selector. The clock frequency that drives the RTI circuit is $f_{OP}/2^{14}$ (or $f_{OP}/16384$), with three additional divider stages, giving a maximum interrupt period of 4 seconds at a bus frequency (f_{OP}) of 32kHz. Register details are given in Section 5.3.

5.2 Computer operating properly (COP) watchdog timer

The COP watchdog timer function is implemented by taking the output of the RTI circuit and further dividing it by eight, as shown in Figure 5-1. Note that the minimum COP timeout period is seven

times the RTI period. This is because the COP will be cleared asynchronously with respect to the value in the core timer counter register/RTI divider, hence the actual COP timeout period will vary between 7x and 8x the RTI period.

The COP function is a mask option, enabled or disabled during device manufacture. *On the MC68HC705P3, the COP function is controlled using the OPTCOP bit in the options register (OPT) (see Section 1.3).*

If the COP circuit times out, an internal reset is generated and the normal reset vector is fetched. A COP timeout is prevented by writing a '0' to bit 0 of address \$0FF0. When the COP is cleared, only the final divide-by-eight stage is cleared (see Figure 5-1).

5.3 Core timer registers

5.3.1 Core timer control and status register (CTCSR)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Core timer control/status (CTCSR)	\$0008	CTOF	RTIF	CTOFE	RTIE	0	0	RT1	RT0	0000 0011

CTOF — Core timer overflow

- 1 (set) — Core timer overflow has occurred.
- 0 (clear) — No core timer overflow interrupt has been generated.

This bit is set when the core timer counter register rolls over from \$FF to \$00; an interrupt request will be generated if CTOFE is set. When set, the bit may be cleared by writing a '0' to it.

RTIF — Real time interrupt flag

- 1 (set) — A real time interrupt has occurred.
- 0 (clear) — No real time interrupt has been generated.

This bit is set when the output of the chosen stage becomes active; an interrupt request will be generated if RTIE is set. When set, the bit may be cleared by writing a '0' to it.

CTOFE — Core timer overflow enable

- 1 (set) — Core timer overflow interrupt is enabled.
- 0 (clear) — Core timer overflow interrupt is disabled.

Setting this bit enables the core timer overflow Interrupt. A CPU interrupt request will then be generated whenever the CTOF bit becomes set and the I-bit in the CCR is clear. Clearing this bit disables the core timer overflow interrupt capability.

RTIE — Real time interrupt enable

- 1 (set) – Real time interrupt is enabled.
- 0 (clear) – Real time interrupt is disabled.

Setting this bit enables the real time interrupt. A CPU interrupt request will then be generated whenever the RTIF bit becomes set and the I-bit in the CCR is clear. Clearing this bit disables the real time interrupt capability.

RT1:RT0 — Real time interrupt rate select

These two bits select one of four taps from the real time interrupt circuitry. Reset sets both RT0 and RT1 to one, selecting the lowest periodic rate and therefore the maximum time in which to alter them if necessary. The COP reset times are also determined by these two bits. Care should be taken when altering RT0 and RT1 if a timeout is imminent, or the timeout period is uncertain. If the selected tap is modified during a cycle in which the counter is switching, an RTIF could be missed or an additional one could be generated. To avoid problems, the COP should be cleared before changing the RTI taps. See Table 5-1 for some example RTI periods.

Table 5-1 Example RTI periods

			Bus frequency f _{OP} = 2 MHz	
RT1	RT0	Division ratio	RTI period	Minimum COP period
0	0	2 ¹⁴	8.2ms	57.3ms
0	1	2 ¹⁵	16.4ms	114.7ms
1	0	2 ¹⁶	32.8ms	229.4ms
1	1	2 ¹⁷	65.5ms	458.8ms

5.3.2 Core timer counter register (CTCR)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Core timer counter (CTCR)	\$0009									0000 0000

The core timer counter register is a read-only register, which contains the current value of the 8-bit ripple counter at the beginning of the timer chain. Reset clears this register.

5.4 Core timer during WAIT

The CPU clock halts during the WAIT mode, but the timer remains active. If the CTIMER interrupts are enabled, then a CTIMER interrupt will cause the processor to exit the WAIT mode.

5.5 Core timer during STOP

The timer is cleared when going into STOP mode. When STOP is exited by an external interrupt or an external reset, the internal oscillator will restart, followed by an internal processor stabilization delay (t_{PORL}). The timer is then cleared and operation resumes.

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PROGRAMMABLE TIMER

Besides the core timer the MC68HC05P3 has a 16-bit programmable timer. This timer consists of a 16-bit read-only free-running counter, with a fixed divide-by-four prescaler, plus the input capture/output compare circuitry. Selected input edges cause the current counter value to be latched into a 16-bit input capture register so that software can later read this value to determine when the edge occurred. When the free running counter value matches the value in the output compare registers, the programmed pin action takes place. Refer to Figure 6-1 for a block diagram of the timer. The timer must be enabled by setting the TIMEN bit in the keyboard/timer register (KEY/TIM).

The timer has a 16-bit architecture, hence each specific functional segment is represented by two 8-bit registers. These registers contain the high and low byte of that functional segment. Accessing the low byte of a specific timer function allows full control of that function; however, an access of the high byte inhibits that specific timer function until the low byte is also accessed.

Note: The I-bit in the CCR should be set while manipulating both the high and low byte register of a specific timer function to ensure that an interrupt does not occur.

6.1 Keyboard/timer register (KEY/TIM)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Keyboard/timer (KEY/TIM)	\$000A						TIMEN	KSF	KIE	---- -000

TIMEN — Timer enable

- 1 (set) — 16-bit timer enabled.
- 0 (clear) — 16-bit timer disabled.

When set the TIMEN bit enables the 16-bit programmable timer and selects the timer functions on the shared PC0/TCAP and PC1/TCMP pins. When this bit is cleared the timer is disabled, and the PC0 and PC1 pins revert to their I/O port functions. TCAP is used for monitoring the external signal; TCMP is used to output the compare signal.

Note: When the timer is enabled, the port pins PC0 and PC1 lose their normal I/O functions.

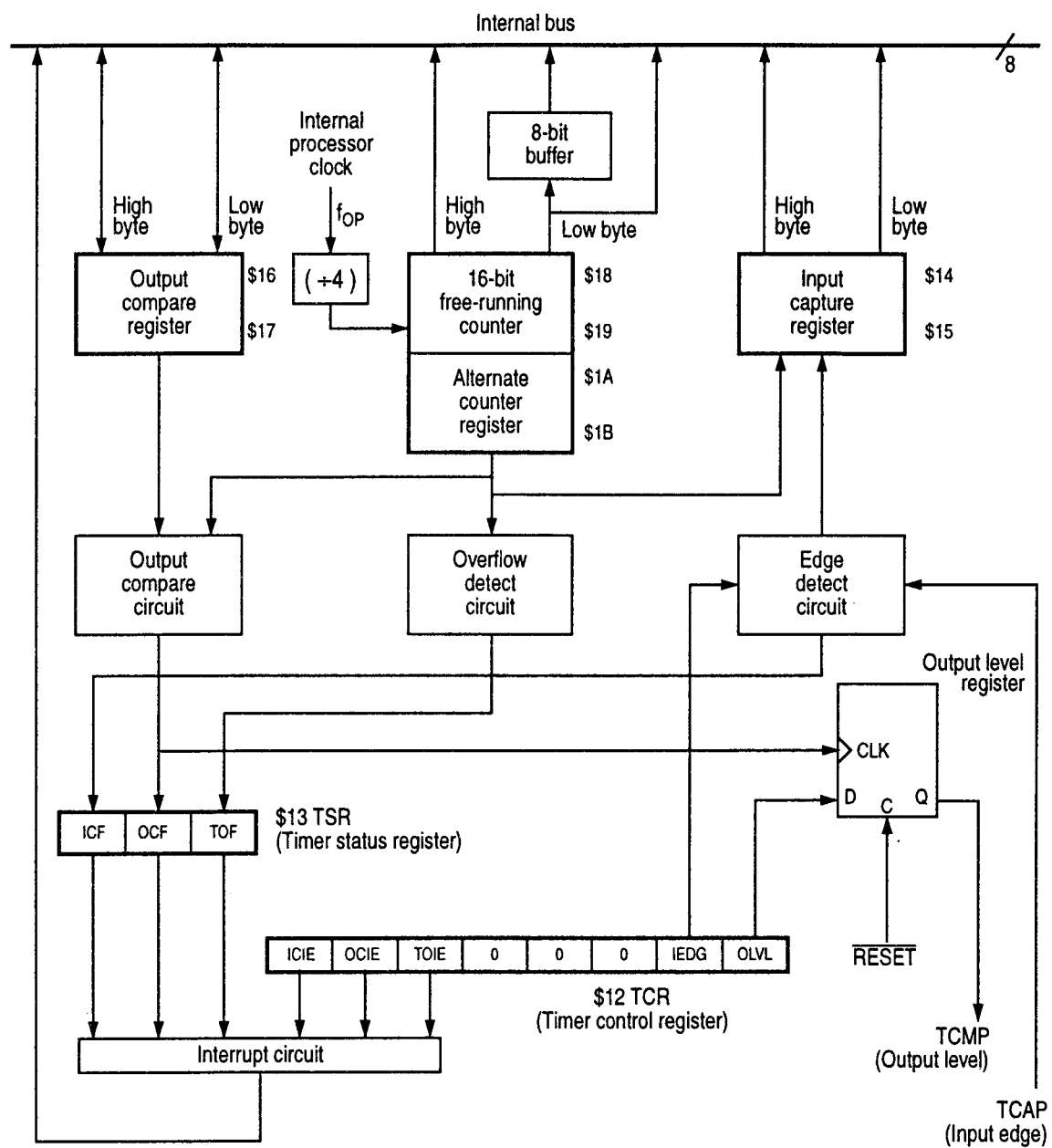


Figure 6-1 16-bit programmable timer block diagram

KSF — Keyboard interrupt status flag

- 1 (set) — A valid transition has occurred on one of the port pins.
- 0 (clear) — No valid transition has occurred on any of the port pins.

For further information see Section 4.4.3.

KIE — Keyboard interrupt enable

- 1 (set) — Keyboard interrupt enabled.
 0 (clear) — Keyboard interrupt disabled.

For further information see Section 4.4.3.

6.2 Counter

The key element in the programmable timer is a 16-bit, free-running counter, or counter register, preceded by a prescaler that divides the internal processor clock by four. The prescaler gives the timer a resolution of 2 μ s if the internal bus clock is 2MHz. The counter is incremented during the low portion of the internal bus clock. Software can read the counter at any time without affecting its value.

6.2.1 Counter high register Counter low register Alternate counter high register Alternate counter low register

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Timer counter high (TCH)	\$0018	(bit 15)							(bit 8)	\$FF
Timer counter low (TCL)	\$0019									\$FC
Alternate counter high (ACH)	\$001A	(bit 15)							(bit 8)	\$FF
Alternate counter low (ACL)	\$001B									\$FC

The double-byte, free-running counter can be read from either of two locations, \$18 – \$19 (counter register) or \$1A – \$1B (alternate counter register). A read from only the less significant byte (LSB) of the free-running counter (\$19 or \$1B) receives the count value at the time of the read. If a read of the free-running counter or alternate counter register first addresses the more significant byte (MSB) (\$18 or \$1A), the LSB is transferred to a buffer. This buffer value remains fixed after the first MSB read, even if the user reads the MSB several times. This buffer is accessed when reading the free-running counter or alternate counter register LSB and thus completes a read sequence of the total counter value. In reading either the free-running counter or alternate counter register, if the MSB is read, the LSB must also be read to complete the sequence. If the timer overflow flag (TOF) is set when the counter register LSB is read, then a read of the TSR will clear the flag.

The alternate counter register differs from the counter register only in that a read of the LSB does not clear TOF. Therefore, to avoid the possibility of missing timer overflow interrupts due to clearing of TOF, the alternate counter register should be used where this is a critical issue.

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The free-running counter is set to \$FFFC during reset and is always a read-only register. During a power-on reset, the counter is also preset to \$FFFC and begins running after the oscillator start-up delay. Because the free-running counter is 16 bits preceded by a fixed divide-by-four prescaler, the value in the free-running counter repeats every 262 144 internal bus clock cycles. TOF is set when the counter overflows (from \$FFFF to \$0000); this will cause an interrupt if TOIE is set.

Bits 8 – 15 — MSB of counter/alternate counter register

A read of only the more significant byte (MSB) transfers the LSB to a buffer, which remains fixed after the first MSB read, until the LSB is also read.

Bits 0 – 7 — LSB of counter/alternate counter register

A read of only the less significant byte (LSB) receives the count value at the time of reading.

6.3 Timer functions

The 16-bit programmable timer is monitored and controlled by a group of ten registers, full details of which are contained in the following paragraphs. An explanation of the timer functions is also given.

6.3.1 Timer control register (TCR)

The timer control register at location \$12 is used to enable the input capture (ICIE), output compare (OCIE), and timer overflow (TOIE) interrupt enable functions as well as selecting input edge sensitivity (IEDG) and output level polarity (OLVL).

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Timer control (TCR)	\$0012	ICIE	OCIE	TOIE				IEDG	OLVL	000 - - - 00

ICIE — Input capture interrupt enable

- 1 (set) — Input capture interrupt enabled.
- 0 (clear) — Input capture interrupt disabled.

OCIE — Output compare interrupt enable

- 1 (set) — Output compare interrupt enabled.
- 0 (clear) — Output compare interrupt disabled.

TOIE — Timer overflow interrupt enable

- 1 (set) – Timer overflow interrupt enabled.
- 0 (clear) – Timer overflow interrupt disabled.

IEDG — Input edge

- 1 (set) – TCAP is positive-going edge sensitive.
- 0 (clear) – TCAP is negative-going edge sensitive.

When IEDG is set, a positive-going edge on the TCAP pin will trigger a transfer of the free-running counter value to the input capture register. When clear, a negative-going edge triggers the transfer.

OLVL — Output level

- 1 (set) – A high output level will appear on the TCMP pin.
- 0 (clear) – A low output level will appear on the TCMP pin.

When OLVL is set, a high output level will be clocked into the output level register by the next successful output compare, and will appear on the TCMP pin. When clear, it will be a low level that will appear on the TCMP pin.

6.3.2 Timer status register (TSR)

The timer status register at location \$13 contains the status bits for the above three interrupt conditions — ICF, OCF, TOF.

Accessing the timer status register satisfies the first condition required to clear the status bits. The remaining step is to access the register corresponding to the status bit.

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Timer status (TSR)	\$0013	ICF	OCF	TOF						uuu - - - -

ICF — Input capture flag

- 1 (set) — A valid input capture has occurred.
- 0 (clear) — No input capture has occurred.

This bit is set when the selected polarity of edge is detected by the input capture edge detector; an input capture interrupt will be generated, if ICIE is set. ICF is cleared by reading the TSR and then the input capture low register at location \$15.

OCF — Output compare flag

- 1 (set) — A valid output compare has occurred.
- 0 (clear) — No output compare has occurred.

This bit is set when the output compare register contents match those of the free-running counter; an output compare interrupt will be generated, if OCIE is set. OCF is cleared by reading the TSR and then the output compare low register at location \$17.

TOF — Timer overflow flag

- 1 (set) — Timer overflow has occurred.
- 0 (clear) — No timer overflow has occurred.

This bit is set when the free-running counter overflows from \$FFFF to \$0000; a timer overflow interrupt will occur, if TOIE is set. TOF is cleared by reading the TSR and the counter low register at location \$19.

When using the timer overflow function and reading the free-running counter at random times to measure an elapsed time, a problem may occur whereby the timer overflow flag is unintentionally cleared if:

- 1) the timer status register is read or written when TOF is set, **and**
- 2) the LSB of the free-running counter is read, but not for the purpose of servicing the flag.

Reading the alternate counter register instead of the counter register will avoid this potential problem.

6.3.3 Input capture function

'Input capture' is a technique whereby an external signal (connected to the TCAP pin) is used to trigger a read of the free-running counter. In this way it is possible to relate the timing of an external signal to the internal counter value, and hence to elapsed time.

6.3.4 Input capture high register
Input capture low register

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Input capture high (ICH)	\$0014	(bit 15)							(bit 8)	undefined
Input capture low (ICL)	\$0015									undefined

The two 8-bit registers that make up the 16-bit input capture register are read-only, and are used to latch the value of the free-running counter after the input capture edge detector senses a valid transition. The level transition that triggers the counter transfer is defined by the input edge bit (IEDG). The most significant 8 bits are stored in the input capture high register at \$14, the least significant in the input capture low register at \$15.

The result obtained from an input capture will be one greater than the value of the free-running counter on the rising edge of the internal bus clock preceding the external transition. This delay is required for internal synchronization. Resolution is one count of the free-running counter, which is four internal bus clock cycles. The free-running counter contents are transferred to the input capture register on each valid signal transition whether the input capture flag (ICF) is set or clear. The input capture register always contains the free-running counter value that corresponds to the most recent input capture. After a read of the input capture register MSB at location \$14, the counter transfer is inhibited until the LSB at location \$15 is also read. This characteristic causes the time used in the input capture software routine and its interaction with the main program to determine the minimum pulse period. A read of the input capture register LSB at location \$15 does not inhibit the free-running counter transfer since the two actions occur on opposite edges of the internal bus clock.

Reset does not affect the contents of the input capture register, except when exiting STOP mode.

6.3.5 Output compare function

'Output compare' is a technique that may be used, for example, to generate an output waveform, or to signal when a specific time period has elapsed, by presetting the output compare register to the appropriate value.

6.3.6 Output compare high register
Output compare low register

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
Output compare high (OCH)	\$0016	(bit 15)							(bit 8)	undefined
Output compare low (OCL)	\$0017									undefined

The 16-bit output compare register is made up of two 8-bit registers at locations \$16 (MSB) and \$17 (LSB). The contents of the output compare register are continually compared with the contents of the free-running counter and, if a match is found, the output compare flag (OCF) in the timer status register is set and the output level (OLVL) bit clocked to the output level register. The output compare register values and the output level bit should be changed after each successful comparison to establish a new elapsed timeout. An interrupt can also accompany a successful output compare provided the corresponding interrupt enable bit (OCIE) is set. (The free-running counter is updated every four internal bus clock cycles.)

After a processor write cycle to the output compare register containing the MSB at location \$16, the output compare function is inhibited until the LSB at location \$17 is also written. The user must write both bytes (locations) if the MSB is written first. A write made only to the LSB at location \$17 will not inhibit the compare function. The processor can write to either byte of the output compare register without affecting the other byte. The output level (OLVL) bit is clocked to the output level register whether the output compare flag (OCF) is set or clear. The minimum time required to update the output compare register is a function of the program rather than the internal hardware. Because the output compare flag and the output compare register are not defined at power on, and not affected by reset, care must be taken when initializing output compare functions with software. The following procedure is recommended:

- 1) write to output compare high to inhibit further compares;
- 2) read the timer status register to clear OCF (if set);
- 3) write to output compare low to enable the output compare function.

All bits of the output compare register are readable and writable and are not altered by the timer hardware or reset. If the compare function is not needed, the two bytes of the output compare register can be used as storage locations.

6.4 Timer during WAIT mode

All CPU action is suspended, but the timers (core and 16-bit) remain active. An interrupt from either of the timers, if enabled, will cause the MCU to exit WAIT mode.

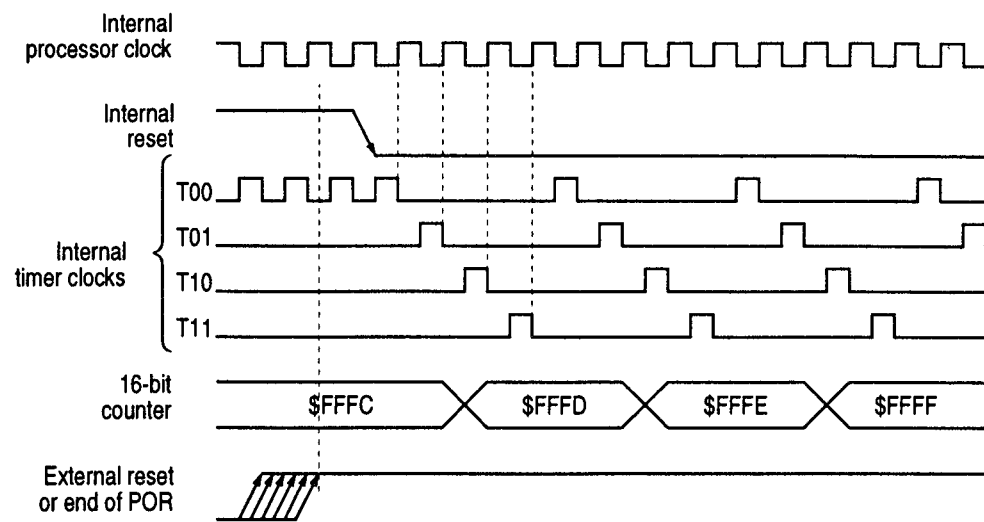
6.5 Timer during STOP mode

In the STOP mode all MCU clocks are stopped, hence the timer stops counting. If STOP is exited by an interrupt the counter retains the last count value. If the device is reset, then the counter is forced to \$FFFC. During STOP, if at least one valid input capture edge occurs at the TCAP pin, the input capture detect circuit is armed. This does not set any timer flags nor wake up the MCU. When the MCU does wake up, however, there is an active input capture flag and data from the first valid edge that occurred during the STOP period. If the device is reset to exit STOP mode, then no input capture flag or data remains, even if a valid input capture edge occurred.

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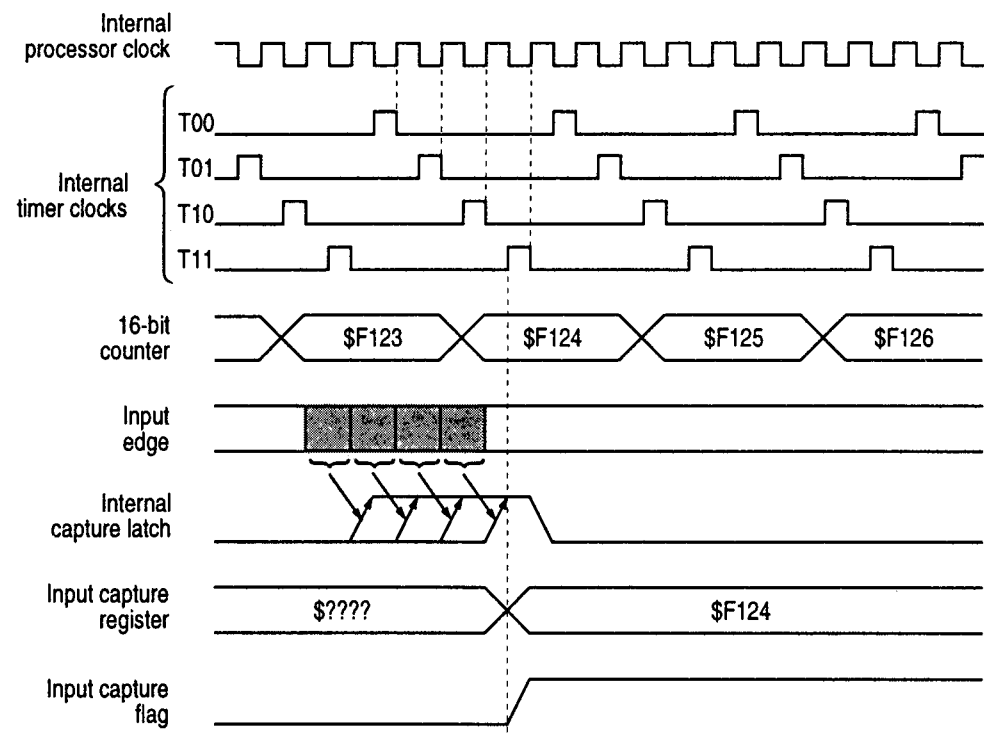
6.6 Timer state diagrams

The relationships between the internal clock signals, the counter contents and the status of the flag bits are shown in the following diagrams. It should be noted that the signals labelled 'internal' (processor clock, timer clocks and reset) are not available to the user.



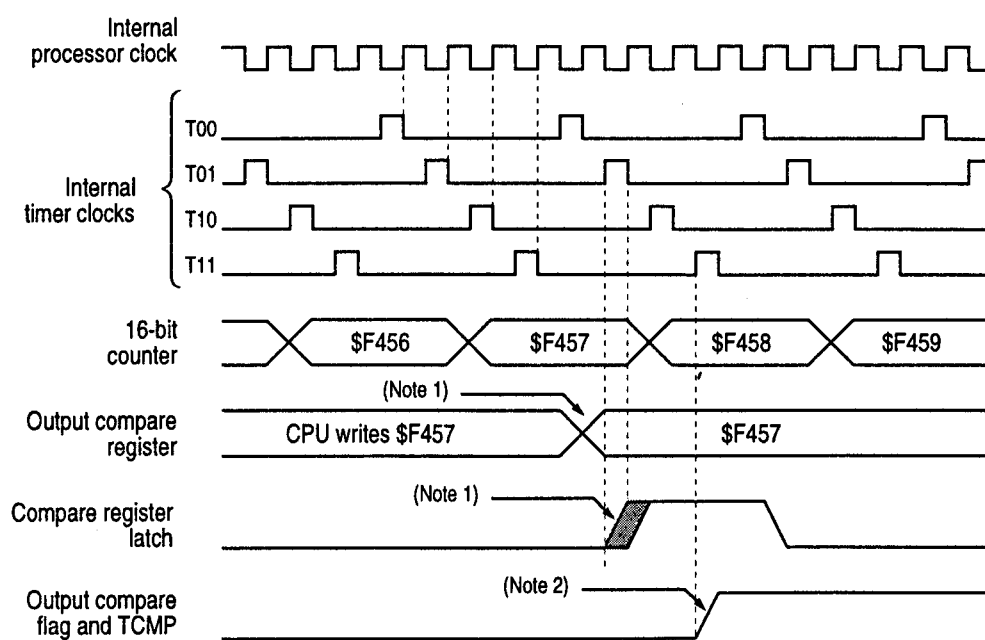
Note: The counter and timer control registers are the only ones affected by power-on or external reset.

Figure 6-2 Timer state timing diagram for reset



Note: If the input edge occurs in the shaded area from one timer state T10 to the next timer state T10, then the input capture flag will be set during the next T11 state.

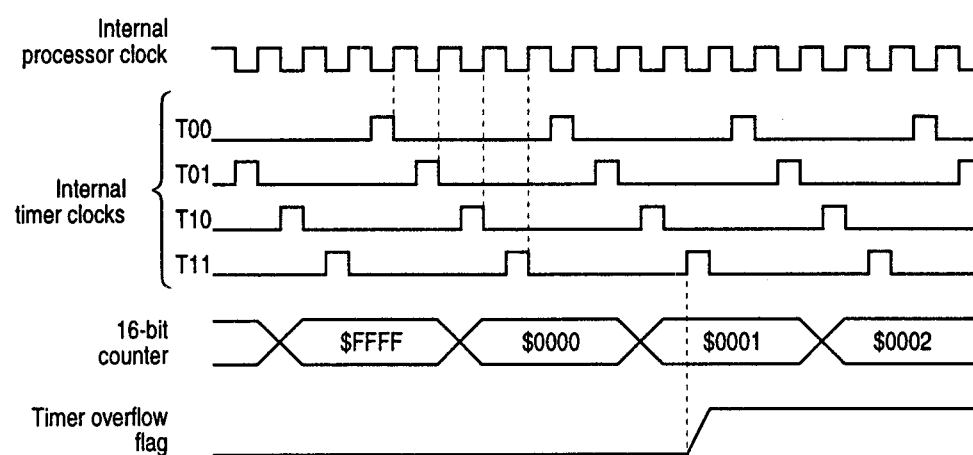
Figure 6-3 Timer state timing diagram for input capture



Note: (1) The CPU write to the compare registers may take place at any time, but a compare only occurs at timer state T01. Thus a four cycle difference may exist between the write to the compare register and the actual compare.

(2) The output compare flag is set at the timer state T11 that follows the comparison match (\$F457 in this example).

Figure 6-4 Timer state timing diagram for output compare



Note: The timer overflow flag is set at timer state T11 (transition of counter from \$FFFF to \$0000). It is cleared by a read of the timer status register during the internal processor clock high time, followed by a read of the counter low register.

Figure 6-5 Timer state timing diagram for timer overflow

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RESETS AND INTERRUPTS

7.1 Resets

The MC68HC05P3 can be reset in four ways: by the initial power-on reset function, by an active low input to the $\overline{\text{RESET}}$ pin, by an opcode fetch from an illegal address, and by a COP watchdog timer reset. Any of these resets will cause the program to return to its starting address, specified by the contents of memory locations \$0FFE to \$0FFF, and cause the interrupt mask of the CCR to be set.

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7.1.1 Power-on reset

A power-on reset occurs when a positive transition is detected on VDD. The power-on reset function is strictly for power turn-on conditions and should not be used to detect drops in the power supply voltage. The power-on circuitry provides a stabilization delay (t_{PORL}) from when the oscillator becomes active. If the external $\overline{\text{RESET}}$ pin is low at the end of this delay then the processor remains in the reset state until $\overline{\text{RESET}}$ goes high. The user must ensure that the voltage on VDD has risen to a point where the MCU can operate properly by the time t_{PORL} has elapsed. If there is doubt, the external $\overline{\text{RESET}}$ pin should remain low until the voltage on VDD has reached the specified minimum operating voltage. This may be accomplished by connecting an external RC-circuit to this pin to generate a power-on reset (POR). In this case, the time constant must be great enough (at least 100ms) to allow the oscillator circuit to stabilize.

7.1.2 $\overline{\text{RESET}}$ pin

When the oscillator is running in a stable state, the MCU is reset when a logic zero is applied to the $\overline{\text{RESET}}$ input for a minimum period of 1.5 machine cycles (t_{CYC}). This pin contains an internal Schmitt trigger as part of its input to improve noise immunity. When the reset pin goes high, the MCU will resume operation on the following cycle.

7.1.3 Illegal address reset

When an opcode fetch occurs from an address which is not part of the RAM (\$0080 – \$00FF) or of the ROM/EPROM (\$0300 – \$0EFF and \$0FF6 – \$0FFF) or EEPROM (\$0100 – \$017F), the device is automatically reset.

Note: No RTS or RTI instruction should be placed at the end of a memory block, e.g. at address \$017F, since this could result in an illegal address reset.

7.1.4 Computer operating properly (COP) reset

The MCU contains a watchdog timer that automatically times out if not reset (cleared) within a specific time by a program reset sequence.

Note: COP timeout is prevented by periodically writing a '0' to bit 0 of address \$1FF0.

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If the COP watchdog timer is allowed to timeout, an internal reset is generated to reset the MCU. Because the internal reset signal is used, the MCU comes out of a COP reset in the same operating mode it was in when the COP timeout was generated.

The COP function is a mask option, enabled or disabled during device manufacture. *On the MC68HC705P3, the COP function is controlled using the OPTCOP bit in the options register (OPT) (see Section 1.3).*

Refer to Section 5.2 for more information on the COP watchdog timer.

7.2 Interrupts

The MCU can be interrupted by five different sources, four maskable hardware interrupts and one non-maskable software interrupt:

- External signal on the $\overline{\text{IRQ}}$ pin; $\overline{\text{IRQ}}$ is mask selectable as edge or edge-and-level sensitive (see Section 1.2 and Section 1.3)
- Keyboard interrupt
- Core timer interrupt
- 16-bit programmable timer interrupt
- Software interrupt instruction (SWI)

Interrupts cause the processor to save the register contents on the stack and to set the interrupt mask (I-bit) to prevent additional interrupts. The RTI instruction (return from interrupt) causes the

register contents to be recovered from the stack and normal processing to resume. While executing the RTI instruction, the interrupt mask bit (I-bit) will be cleared providing the corresponding enable bit stored on the stack is zero, i.e. the interrupt is disabled.

Unlike reset, hardware interrupts do not cause the current instruction execution to be halted, but are considered pending until the current instruction is complete. The current instruction is the one already fetched and being operated on. When the current instruction is complete, the processor checks all pending hardware interrupts. If interrupts are not masked (CCR I-bit clear) and the corresponding interrupt enable bit is set, the processor proceeds with interrupt processing; otherwise, the next instruction is fetched and executed. Figure 7-1 shows the interrupt processing flow.

Note: Power-on or external reset clears all interrupt enable bits thus preventing interrupts during the reset sequence.

7.2.1 Interrupt priorities

Each potential interrupt source is assigned a priority which means that if more than one interrupt is pending at the same time, the processor will service the one with the highest priority first. For example, if both an external interrupt and a timer interrupt are pending after an instruction execution, the external interrupt is serviced first. Table 7-1 shows the relative priority of all the possible interrupt sources.

Table 7-1 Interrupt priorities

Source	Register	Flags	Vector address	Priority
Reset	—	—	\$0FFE, \$0FFF	<div>highest</div> <div>↑</div> <div>lowest</div>
Software interrupt (SWI)	—	—	\$0FFC, \$0FFD	
External interrupt (IRQ) / keyboard interrupt	KEY/TIM	KSF	\$0FFA, \$0FFB	
Core timer	CTCSR	CTOF, RTIF	\$0FF8, \$0FF9	
Programmable timer	TSR	TOF, ICF, OCF	\$0FF6, \$0FF7	

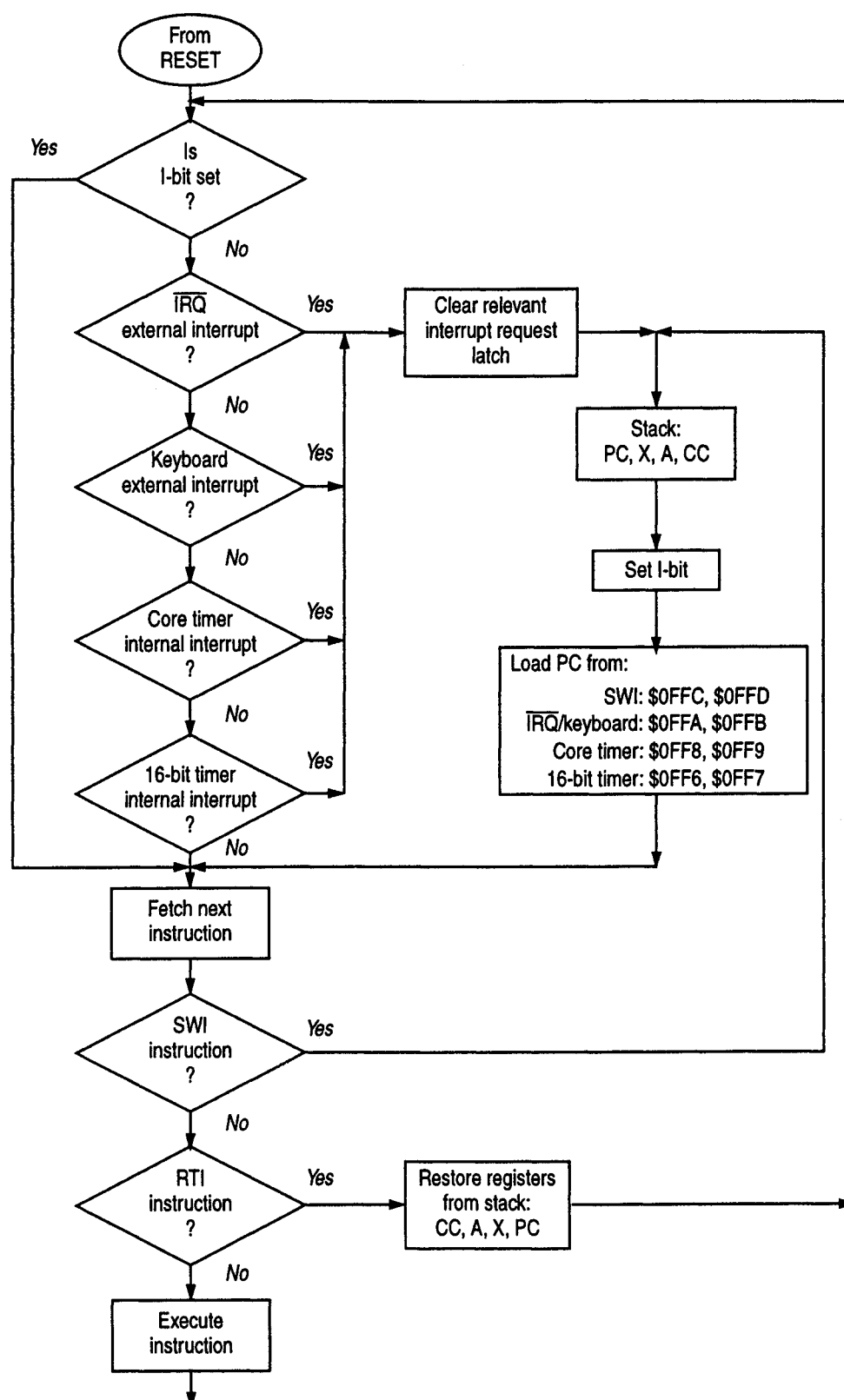


Figure 7-1 Interrupt flowchart

7.2.2 Non-maskable software interrupt (SWI)

The software interrupt (SWI) is an executable instruction and a nonmaskable interrupt: it is executed regardless of the state of the I-bit in the CCR. If the I-bit is zero (interrupts enabled), SWI is executed after interrupts that were pending when the SWI was fetched, but before interrupts generated after the SWI was fetched. The SWI interrupt service routine address is specified by the contents of memory locations \$0FFC and \$0FFD.

7.2.3 Maskable hardware interrupts

If the interrupt mask bit (I-bit) of the CCR is set, all maskable interrupts (internal and external) are masked. Clearing the I-bit allows interrupt processing to occur. \overline{IRQ} is mask selectable as either edge or edge-and-level sensitive (see Section 1.2 and Section 1.3)

Note: The internal interrupt latch is cleared in the first part of the interrupt service routine; therefore, one external interrupt pulse could be latched and serviced as soon as the I-bit is cleared.

7.2.3.1 Real time and core timer (CTIMER) interrupts

There are two different core timer interrupt flags that cause a CTIMER interrupt whenever an interrupt is enabled and its flag becomes set, namely RTIF and CTOF. The interrupt flags and enable bits are located in the CTIMER control and status register (CTCSR). These interrupts will vector to the same interrupt service routine, whose start address is contained in memory locations \$0FF8 and \$0FF9 (see Section 5.3.1 and Figure 5-1).

To make use of the real time interrupt the RTIE bit must first be set. The RTIF bit will then be set after the specified number of counts.

To make use of the core timer overflow interrupt, the CTOFE bit must first be set. The CTOF bit will then be set when the core timer counter register overflows from \$FF to \$00.

7.2.3.2 Programmable 16-bit timer interrupt

There are three different timer interrupt flags (ICF, OCF, TOF) that cause a timer interrupt whenever they are set and enabled. The timer interrupt enable bits (ICIE, OCIE, TOIE) are located in the timer control register (TCR) and the timer interrupt flag is located in the timer status register (TSR). All three interrupts will vector to the same service routine, whose start address is contained in memory locations \$0FF6 and \$0FF7.

7.2.3.3 Keyboard interrupt

When configured as input pins, Port C bits 0-5 provide a wired-OR keyboard interrupt facility and will generate an interrupt, provided that the keyboard interrupt enable bit (KIE) in the keyboard/timer register (KEY/TIM) is set. The address of the interrupt service routine is specified by the contents of memory locations \$0FFA and \$0FFB. Since this interrupt vector is shared with the IRQ external interrupt function the interrupt service routine should check KSF to determine the interrupt source. KSF should be cleared by software in the interrupt service routine. Care must be taken to allow adequate time for switch debounce before clearing the flag.

7.2.4 Hardware controlled interrupt sequence

The following three functions (RESET, STOP, and WAIT) are not in the strictest sense interrupts. However, they are acted upon in a similar manner. Flowcharts for STOP and WAIT are shown in Section 2.3, Figure 2-2.

RESET: A reset condition causes the program to vector to its starting address, which is contained in memory locations \$0FFE (MSB) and \$0FFF (LSB). The I-bit in the condition code register is also set, to disable interrupts.

STOP: The STOP instruction causes the oscillator to be turned off and the processor to 'sleep' until an external interrupt ($\overline{\text{IRQ}}$) or a keyboard interrupt occurs, or the device is reset.

WAIT: The WAIT instruction causes all processor clocks to stop, but leaves the timer clocks running. This 'rest' state of the processor can be cleared by reset, an external interrupt ($\overline{\text{IRQ}}$), a keyboard interrupt, or a timer interrupt (core or 16-bit). There are no special WAIT vectors for these interrupts.

8

CPU CORE AND INSTRUCTION SET

This section provides a description of the CPU core registers, the instruction set and the addressing modes of the MC68HC05P3.

8.1 Registers

The MCU contains five registers, as shown in the programming model of Figure 8-1. The interrupt stacking order is shown in Figure 8-2.

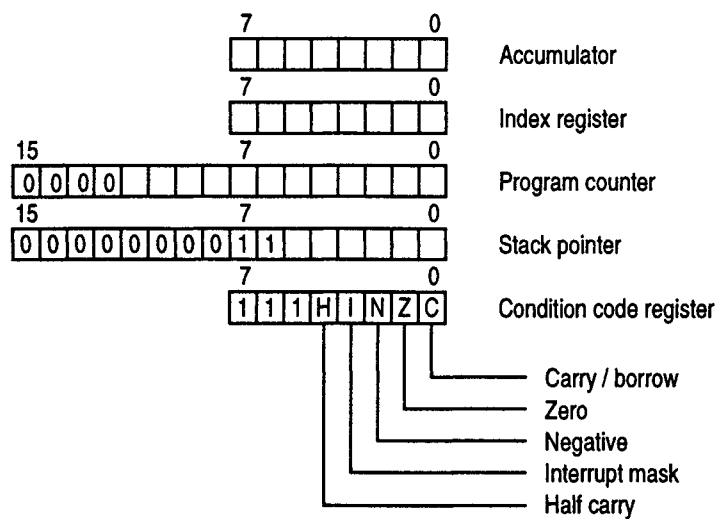


Figure 8-1 Programming model

8.1.1 Accumulator (A)

The accumulator is a general purpose 8-bit register used to hold operands and results of arithmetic calculations or data manipulations.

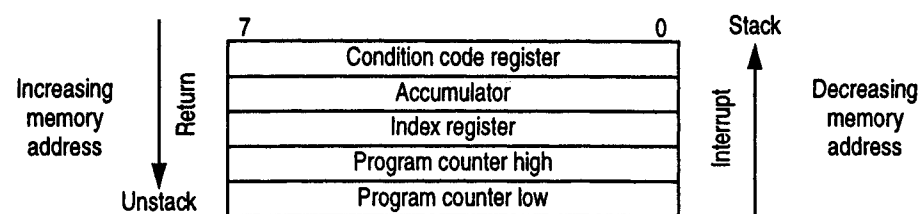


Figure 8-2 Stacking order

8.1.2 Index register (X)

The index register is an 8-bit register, which can contain the indexed addressing value used to create an effective address. The index register may also be used as a temporary storage area.

8.1.3 Program counter (PC)

The program counter is a 16-bit register, which contains the address of the next byte to be fetched. Although the M68HC05 CPU core can address 64K bytes of memory, the actual address range of the MC68HC05P3 is limited to 4K bytes. The four most significant bits of the program counter are therefore not used and are permanently set to zero.

8.1.4 Stack pointer (SP)

The stack pointer is a 16-bit register, which contains the address of the next free location on the stack. During an MCU reset or the reset stack pointer (RSP) instruction, the stack pointer is set to location \$00FF. The stack pointer is then decremented as data is pushed onto the stack and incremented as data is pulled from the stack.

When accessing memory, the ten most significant bits are permanently set to 0000000011. These ten bits are appended to the six least significant register bits to produce an address within the range of \$00C0 to \$00FF. Subroutines and interrupts may use up to 64 (decimal) locations. If 64 locations are exceeded, the stack pointer wraps around and overwrites the previously stored information. A subroutine call occupies two locations on the stack; an interrupt uses five locations.

8.1.5 Condition code register (CCR)

The CCR is a 5-bit register in which four bits are used to indicate the results of the instruction just executed, and the fifth bit indicates whether interrupts are masked. These bits can be individually tested by a program, and specific actions can be taken as a result of their state. Each bit is explained in the following paragraphs.

Half carry (H)

This bit is set during ADD and ADC operations to indicate that a carry occurred between bits 3 and 4.

Interrupt (I)

When this bit is set, all maskable interrupts are masked. If an interrupt occurs while this bit is set, the interrupt is latched and remains pending until the interrupt bit is cleared.

Negative (N)

When set, this bit indicates that the result of the last arithmetic, logical, or data manipulation was negative.

Zero (Z)

When set, this bit indicates that the result of the last arithmetic, logical, or data manipulation was zero.

Carry/borrow (C)

When set, this bit indicates that a carry or borrow out of the arithmetic logical unit (ALU) occurred during the last arithmetic operation. This bit is also affected during bit test and branch instructions and during shifts and rotates.

8.2 Instruction set

The MCU has a set of 62 basic instructions. They can be grouped into five different types as follows:

- Register/memory
- Read/modify/write
- Branch
- Bit manipulation
- Control

The following paragraphs briefly explain each type. All the instructions within a given type are presented in individual tables.

This MCU uses all the instructions available in the M146805 CMOS family plus one more: the unsigned multiply (MUL) instruction. This instruction allows unsigned multiplication of the contents of the accumulator (A) and the index register (X). The high-order product is then stored in the index register and the low-order product is stored in the accumulator. A detailed definition of the MUL instruction is shown in Table 8-1.

8.2.1 Register/memory Instructions

Most of these instructions use two operands. The first operand is either the accumulator or the index register. The second operand is obtained from memory using one of the addressing modes. The jump unconditional (JMP) and jump to subroutine (JSR) instructions have no register operand. Refer to Table 8-2 for a complete list of register/memory instructions.

8.2.2 Branch instructions

These instructions cause the program to branch if a particular condition is met; otherwise, no operation is performed. Branch instructions are two-byte instructions. Refer to Table 8-3.

8.2.3 Bit manipulation instructions

The MCU can set or clear any writable bit that resides in the first 256 bytes of the memory space (page 0). All port data and data direction registers, timer and serial interface registers, control/status registers and a portion of the on-chip RAM reside in page 0. An additional feature allows the software to test and branch on the state of any bit within these locations. The bit set, bit clear, bit test and branch functions are all implemented with single instructions. For the test and branch instructions, the value of the bit tested is also placed in the carry bit of the condition code register. Refer to Table 8-4.

8.2.4 Read/modify/write instructions

These instructions read a memory location or a register, modify or test its contents, and write the modified value back to memory or to the register. The test for negative or zero (TST) instruction is an exception to this sequence of reading, modifying and writing, since it does not modify the value. Refer to Table 8-5 for a complete list of read/modify/write instructions.

8.2.5 Control instructions

These instructions are register reference instructions and are used to control processor operation during program execution. Refer to Table 8-6 for a complete list of control instructions.

8.2.6 Tables

Tables for all the instruction types listed above follow. In addition there is a complete alphabetical listing of all the instructions (see Table 8-7), and an opcode map for the instruction set of the M68HC05 MCU family (see Table 8-8).

Table 8-1 MUL instruction

Operation	X:A ← X*A			
Description	Multiplies the eight bits in the index register by the eight bits in the accumulator and places the 16-bit result in the concatenated accumulator and index register.			
Condition codes	H : Cleared I : Not affected N : Not affected Z : Not affected C : Cleared			
Source	MUL			
Form	Addressing mode Inherent	Cycles 11	Bytes 1	Opcode \$42

Table 8-2 Register/memory instructions

		Addressing modes																	
		Immediate			Direct			Extended			Indexed (no offset)			Indexed (8-bit offset)			Indexed (16-bit offset)		
Function	Mnemonic	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles
Load A from memory	LDA	A6	2	2	B6	2	3	C6	3	4	F6	1	3	E6	2	4	D6	3	5
Load X from memory	LDX	AE	2	2	BE	2	3	CE	3	4	FE	1	3	EE	2	4	DE	3	5
Store A in memory	STA				B7	2	4	C7	3	5	F7	1	4	E7	2	5	D7	3	6
Store X in memory	STX				BF	2	4	CF	3	5	FF	1	4	EF	2	5	DF	3	6
Add memory to A	ADD	AB	2	2	BB	2	3	CB	3	4	FB	1	3	EB	2	4	DB	3	5
Add memory and carry to A	ADC	A9	2	2	B9	2	3	C9	3	4	F9	1	3	E9	2	4	D9	3	5
Subtract memory	SUB	A0	2	2	B0	2	3	C0	3	4	F0	1	3	E0	2	4	D0	3	5
Subtract memory from A with borrow	SBC	A2	2	2	B2	2	3	C2	3	4	F2	1	3	E2	2	4	D2	3	5
AND memory with A	AND	A4	2	2	B4	2	3	C4	3	4	F4	1	3	E4	2	4	D4	3	5
OR memory with A	ORA	AA	2	2	BA	2	3	CA	3	4	FA	1	3	EA	2	4	DA	3	5
Exclusive OR memory with A	EOR	A8	2	2	B8	2	3	C8	3	4	F8	1	3	E8	2	4	D8	3	5
Arithmetic compare A with memory	CMP	A1	2	2	B1	2	3	C1	3	4	F1	1	3	E1	2	4	D1	3	5
Arithmetic compare X with memory	CPX	A3	2	2	B3	2	3	C3	3	4	F3	1	3	E3	2	4	D3	3	5
Bit test memory with A (logical compare)	BIT	A5	2	2	B5	2	3	C5	3	4	F5	1	3	E5	2	4	D5	3	5
Jump unconditional	JMP				BC	2	2	CC	3	3	FC	1	2	EC	2	3	DC	3	4
Jump to subroutine	JSR				BD	2	5	CD	3	6	FD	1	5	ED	2	6	DD	3	7

Table 8-3 Branch instructions

Function	Mnemonic	Relative addressing mode		
		Opcode	# Bytes	# Cycles
Branch always	BRA	20	2	3
Branch never	BRN	21	2	3
Branch if higher	BHI	22	2	3
Branch if lower or same	BLS	23	2	3
Branch if carry clear	BCC	24	2	3
(Branch if higher or same)	(BHS)	24	2	3
Branch if carry set	BCS	25	2	3
(Branch if lower)	(BLO)	25	2	3
Branch if not equal	BNE	26	2	3
Branch if equal	BEQ	27	2	3
Branch if half carry clear	BHCC	28	2	3
Branch if half carry set	BHCS	29	2	3
Branch if plus	BPL	2A	2	3
Branch if minus	BMI	2B	2	3
Branch if interrupt mask bit is clear	BMC	2C	2	3
Branch if interrupt mask bit is set	BMS	2D	2	3
Branch if interrupt line is low	BIL	2E	2	3
Branch if interrupt line is high	BIH	2F	2	3
Branch to subroutine	BSR	AD	2	6

Table 8-4 Bit manipulation instructions

Function	Mnemonic	Addressing modes					
		Bit set/clear			Bit test and branch		
		Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles
Branch if bit n is set	BRSET n (n=0–7)				2•n	3	5
Branch if bit n is clear	BRCLR n (n=0–7)				01+2•n	3	5
Set bit n	BSET n (n=0–7)	10+2•n	2	5			
Clear bit n	BCLR n (n=0–7)	11+2•n	2	5			

Table 8-5 Read/modify/write instructions

		Addressing modes														
		Inherent (A)			Inherent (X)			Direct			Indexed (no offset)			Indexed (8-bit offset)		
		Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles	Opcode	# Bytes	# Cycles
Increment	INC	4C	1	3	5C	1	3	3C	2	5	7C	1	5	6C	2	6
Decrement	DEC	4A	1	3	5A	1	3	3A	2	5	7A	1	5	6A	2	6
Clear	CLR	4F	1	3	5F	1	3	3F	2	5	7F	1	5	6F	2	6
Complement	COM	43	1	3	53	1	3	33	2	5	73	1	5	63	2	6
Negate (two's complement)	NEG	40	1	3	50	1	3	30	2	5	70	1	5	60	2	6
Rotate left through carry	ROL	49	1	3	59	1	3	39	2	5	79	1	5	69	2	6
Rotate right through carry	ROR	46	1	3	56	1	3	36	2	5	76	1	5	66	2	6
Logical shift left	LSL	48	1	3	58	1	3	38	2	5	78	1	5	68	2	6
Logical shift right	LSR	44	1	3	54	1	3	34	2	5	74	1	5	64	2	6
Arithmetic shift right	ASR	47	1	3	57	1	3	37	2	5	77	1	5	67	2	6
Test for negative or zero	TST	4D	1	3	5D	1	3	3D	2	4	7D	1	4	6D	2	5
Multiply	MUL	42	1	11												

Table 8-6 Control instructions

Function	Mnemonic	Inherent addressing mode		
		Opcode	# Bytes	# Cycles
Transfer A to X	TAX	97	1	2
Transfer X to A	TXA	9F	1	2
Set carry bit	SEC	99	1	2
Clear carry bit	CLC	98	1	2
Set interrupt mask bit	SEI	9B	1	2
Clear interrupt mask bit	CLI	9A	1	2
Software interrupt	SWI	83	1	10
Return from subroutine	RTS	81	1	6
Return from interrupt	RTI	80	1	9
Reset stack pointer	RSP	9C	1	2
No-operation	NOP	9D	1	2
Stop	STOP	8E	1	2
Wait	WAIT	8F	1	2

Table 8-7 Instruction set

Mnemonic	Addressing modes										Condition codes				
	INH	IMM	DIR	EXT	REL	IX	IX1	IX2	BSC	BTB	H	I	N	Z	C
ADC												.			
ADD												.			
AND											.	.			.
ASL											.	.			
ASR											.	.			
BCC										
BCLR										
BCS										
BEQ										
BHCC										
BHCS										
BHI										
BHS										
BIH										
BIL										
BIT											.	.			.
BLO										
BLS										
BMC										
BMI										
BMS										
BNE										
BPL										
BRA										
BRN										
BRCLR											
BRSET											
BSET										
BSR										
CLC											0
CLI											.	0	.	.	.
CLR											.	.	0	1	.
CMP											.	.			

Address mode abbreviations				Condition code symbols		
BSC	Bit set/clear	IMM	Immediate	H	Half carry (from bit 3)	Tested and set if true, cleared otherwise
BTB	Bit test & branch	IX	Indexed (no offset)	I	Interrupt mask	• Not affected
DIR	Direct	IX1	Indexed, 1 byte offset	N	Negate (sign bit)	? Load CCR from stack
EXT	Extended	IX2	Indexed, 2 byte offset	Z	Zero	0 Cleared
INH	Inherent	REL	Relative	C	Carry/borrow	1 Set
			Not implemented			

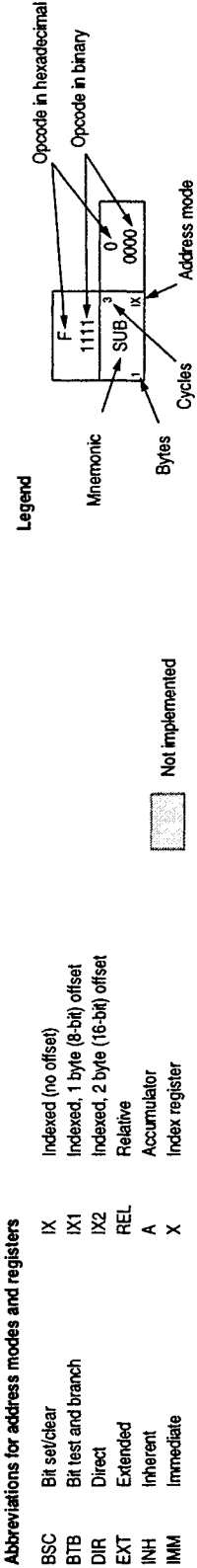
Table 8-7 Instruction set (Continued)

Mnemonic	Addressing modes										Condition codes				
	INH	IMM	DIR	EXT	REL	IX	IX1	IX2	BSC	BTB	H	I	N	Z	C
COM											•	•			1
CPX											•	•			
DEC											•	•			•
EOR											•	•			•
INC											•	•			•
JMP											•	•	•	•	•
JSR											•	•	•	•	•
LDA											•	•			•
LDX											•	•			•
LSL											•	•			
LSR											•	•	0		
MUL											0	•	•	•	0
NEG											•	•			
NOP											•	•	•	•	•
ORA											•	•			•
ROL											•	•			
ROR											•	•			
RSP											•	•	•	•	•
RTI											?	?	?	?	?
RTS											•	•	•	•	•
SBC											•	•			
SEC											•	•	•	•	1
SEI											•	1	•	•	•
STA											•	•			•
STOP											•	0	•	•	•
STX											•	•			•
SUB											•	•			
SWI											•	1	•	•	•
TAX											•	•	•	•	•
TST											•	•			•
TXA											•	•	•	•	•
WAIT											•	0	•	•	•

Address mode abbreviations				Condition code symbols			
BSC	Bit set/clear	IMM	Immediate	H	Half carry (from bit 3)		Tested and set if true, cleared otherwise
BTB	Bit test & branch	IX	Indexed (no offset)	I	Interrupt mask	•	Not affected
DIR	Direct	IX1	Indexed, 1 byte offset	N	Negate (sign bit)	?	Load CCR from stack
EXT	Extended	IX2	Indexed, 2 byte offset	Z	Zero	0	Cleared
INH	Inherent	REL	Relative	C	Carry/borrow	1	Set
<div></div> Not implemented							

Table 8-8 M68HC05 opcode map

Bit manipulation			Branch		Read/modify/write				Control		Register/memory			
BTB	BSC	REL	DIR	INH	INH	IX1	IX	INH	IMM	DIR	EXT	IX2	IX1	IX
0	0000	2	0011	4	5	6	7	8	A	B	C	D	E	F
High														Low
0	BRSET0	BRA	NEG	NEGA	NEGX	NEG	NEG	RTI	SUB	SUB	SUB	SUB	SUB	SUB
0000	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
1	BRCLR0	BRN						RTS	CMP	CMP	CMP	CMP	CMP	CMP
0001	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
2	BRSET1	BHI		MUL					SBC	SBC	SBC	SBC	SBC	SBC
0010	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
3	BRCLR1	BLS	COM	COMA	COMX	COM	COM	SWI	CPX	CPX	CPX	CPX	CPX	CPX
0011	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
4	BRSET2	BCC	LSR	LSRA	LSRX	LSR	LSR		AND	AND	AND	AND	AND	AND
0100	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
5	BRCLR2	BCS							BIT	BIT	BIT	BIT	BIT	BIT
0101	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
6	BRSET3	BNE	ROR	RORA	RORX	ROR	ROR		LDA	LDA	LDA	LDA	LDA	LDA
0110	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
7	BRCLR3	BEQ	ASR	ASRA	ASRX	ASR	ASR	TAX	STA	STA	STA	STA	STA	STA
0111	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
8	BRSET4	BHCC	LSL	LSLA	LSLX	LSL	LSL	CLC	EOR	EOR	EOR	EOR	EOR	EOR
1000	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
9	BRCLR4	BHCS	ROL	ROLA	ROLX	ROL	ROL	SEC	ADC	ADC	ADC	ADC	ADC	ADC
1001	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
A	BRSET5	BPL	DEC	DECA	DECX	DEC	DEC	CLI	ORA	ORA	ORA	ORA	ORA	ORA
1010	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
B	BRCLR5	BMI						SEI	ADD	ADD	ADD	ADD	ADD	ADD
1011	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
C	BRSET6	BMC	INC	INCA	INCX	INC	INC	RSP	JMP	JMP	JMP	JMP	JMP	JMP
1100	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
D	BRCLR6	BMS	TST	TSTA	TSTX	TST	TST	NOP	BSR	BSR	BSR	BSR	BSR	BSR
1101	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
E	BRSET7	BIL						STOP	LDX	LDX	LDX	LDX	LDX	LDX
1110	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3
F	BRCLR7	BIH	CLR	CLRA	CLR X	CLR	CLR	WAIT	STX	STX	STX	STX	STX	STX
1111	BTB 2	REL 2	DIR 2	INH 1	INH 1	IX1 1	IX 1	INH 1	IMM 2	DIR 2	EXT 3	IX2 3	IX1 3	IX 3



8.3 Addressing modes

Ten different addressing modes provide programmers with the flexibility to optimize their code for all situations. The various indexed addressing modes make it possible to locate data tables, code conversion tables and scaling tables anywhere in the memory space. Short indexed accesses are single byte instructions; the longest instructions (three bytes) enable access to tables throughout memory. Short absolute (direct) and long absolute (extended) addressing are also included. One or two byte direct addressing instructions access all data bytes in most applications. Extended addressing permits jump instructions to reach all memory locations.

The term 'effective address' (EA) is used in describing the various addressing modes. The effective address is defined as the address from which the argument for an instruction is fetched or stored. The ten addressing modes of the processor are described below. Parentheses are used to indicate 'contents of' the location or register referred to. For example, (PC) indicates the contents of the location pointed to by the PC (program counter). An arrow indicates 'is replaced by' and a colon indicates concatenation of two bytes. For additional details and graphical illustrations, refer to the *M6805 HMOS/M146805 CMOS Family Microcomputer/Microprocessor User's Manual* or to the *M68HC05 Applications Guide*.

8.3.1 Inherent

In the inherent addressing mode, all the information necessary to execute the instruction is contained in the opcode. Operations specifying only the index register or accumulator, as well as the control instruction, with no other arguments are included in this mode. These instructions are one byte long.

8

8.3.2 Immediate

In the immediate addressing mode, the operand is contained in the byte immediately following the opcode. The immediate addressing mode is used to access constants that do not change during program execution (e.g. a constant used to initialize a loop counter).

$$EA = PC+1; PC \leftarrow PC+2$$

8.3.3 Direct

In the direct addressing mode, the effective address of the argument is contained in a single byte following the opcode byte. Direct addressing allows the user to directly address the lowest 256 bytes in memory with a single two-byte instruction.

$$EA = (PC+1); PC \leftarrow PC+2$$
$$\text{Address bus high} \leftarrow 0; \text{Address bus low} \leftarrow (PC+1)$$

8.3.4 Extended

In the extended addressing mode, the effective address of the argument is contained in the two bytes following the opcode byte. Instructions with extended addressing mode are capable of referencing arguments anywhere in memory with a single three-byte instruction. When using the Motorola assembler, the user need not specify whether an instruction uses direct or extended addressing. The assembler automatically selects the short form of the instruction.

$$\begin{aligned} \text{EA} &= (\text{PC}+1):(\text{PC}+2); \text{PC} \leftarrow \text{PC}+3 \\ \text{Address bus high} &\leftarrow (\text{PC}+1); \text{Address bus low} \leftarrow (\text{PC}+2) \end{aligned}$$

8.3.5 Indexed, no offset

In the indexed, no offset addressing mode, the effective address of the argument is contained in the 8-bit index register. This addressing mode can access the first 256 memory locations. These instructions are only one byte long. This mode is often used to move a pointer through a table or to hold the address of a frequently referenced RAM or I/O location.

$$\begin{aligned} \text{EA} &= \text{X}; \text{PC} \leftarrow \text{PC}+1 \\ \text{Address bus high} &\leftarrow 0; \text{Address bus low} \leftarrow \text{X} \end{aligned}$$

8

8.3.6 Indexed, 8-bit offset

In the indexed, 8-bit offset addressing mode, the effective address is the sum of the contents of the unsigned 8-bit index register and the unsigned byte following the opcode. Therefore the operand can be located anywhere within the lowest 511 memory locations. This addressing mode is useful for selecting the *m*th element in an *n* element table.

$$\begin{aligned} \text{EA} &= \text{X}+(\text{PC}+1); \text{PC} \leftarrow \text{PC}+2 \\ \text{Address bus high} &\leftarrow \text{K}; \text{Address bus low} \leftarrow \text{X}+(\text{PC}+1) \\ \text{where K} &= \text{the carry from the addition of X and (PC+1)} \end{aligned}$$

8.3.7 Indexed, 16-bit offset

In the indexed, 16-bit offset addressing mode, the effective address is the sum of the contents of the unsigned 8-bit index register and the two unsigned bytes following the opcode. This address mode can be used in a manner similar to indexed, 8-bit offset except that this three-byte instruction allows tables to be anywhere in memory. As with direct and extended addressing, the Motorola assembler determines the shortest form of indexed addressing.

$$\begin{aligned} \text{EA} &= \text{X}+[(\text{PC}+1):(\text{PC}+2)]; \text{PC} \leftarrow \text{PC}+3 \\ \text{Address bus high} &\leftarrow (\text{PC}+1)+\text{K}; \text{Address bus low} \leftarrow \text{X}+(\text{PC}+2) \\ \text{where K} &= \text{the carry from the addition of X and (PC+2)} \end{aligned}$$

8.3.8 Relative

The relative addressing mode is only used in branch instructions. In relative addressing, the contents of the 8-bit signed byte (the offset) following the opcode are added to the PC if, and only if, the branch conditions are true. Otherwise, control proceeds to the next instruction. The span of relative addressing is from -126 to +129 from the opcode address. The programmer need not calculate the offset when using the Motorola assembler, since it calculates the proper offset and checks to see that it is within the span of the branch.

$$\begin{aligned} \text{EA} &= \text{PC}+2+(\text{PC}+1); \text{PC} \leftarrow \text{EA} \text{ if branch taken;} \\ &\text{otherwise EA} = \text{PC} \leftarrow \text{PC}+2 \end{aligned}$$

8.3.9 Bit set/clear

In the bit set/clear addressing mode, the bit to be set or cleared is part of the opcode. The byte following the opcode specifies the address of the byte in which the specified bit is to be set or cleared. Any read/write bit in the first 256 locations of memory, including I/O, can be selectively set or cleared with a single two-byte instruction.

$$\begin{aligned} \text{EA} &= (\text{PC}+1); \text{PC} \leftarrow \text{PC}+2 \\ \text{Address bus high} &\leftarrow 0; \text{Address bus low} \leftarrow (\text{PC}+1) \end{aligned}$$

8.3.10 Bit test and branch

The bit test and branch addressing mode is a combination of direct addressing and relative addressing. The bit to be tested and its condition (set or clear) is included in the opcode. The address of the byte to be tested is in the single byte immediately following the opcode byte (EA1). The signed relative 8-bit offset in the third byte (EA2) is added to the PC if the specified bit is set or cleared in the specified memory location. This single three-byte instruction allows the program to branch based on the condition of any readable bit in the first 256 locations of memory. The span of branch is from -125 to +130 from the opcode address. The state of the tested bit is also transferred to the carry bit of the condition code register.

$$\begin{aligned} \text{EA1} &= (\text{PC}+1); \text{PC} \leftarrow \text{PC}+2 \\ \text{Address bus high} &\leftarrow 0; \text{Address bus low} \leftarrow (\text{PC}+1) \\ \text{EA2} &= \text{PC}+3+(\text{PC}+2); \text{PC} \leftarrow \text{EA2} \text{ if branch taken;} \\ &\text{otherwise PC} \leftarrow \text{PC}+3 \end{aligned}$$

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9

ELECTRICAL SPECIFICATIONS

This section contains the electrical specifications and associated timing information for the MC68HC05P3 and target data for the MC68HC705P3.

Important: Information given cannot be guaranteed. All values may change before the MC68HC705P3 is qualified.

9.1 Maximum ratings

Table 9-1 Maximum ratings

Rating ⁽¹⁾	Symbol	Value	Unit
Supply voltage	V _{DD}	− 0.3 to +7.0	V
Input voltage: (Ports, OSC1, RESET, IRQ)	V _{in}	V _{SS} − 0.3 to V _{DD} + 0.3	V
Operating temperature ranges (5V±10%) – standard – extended – extended (not MC68HC705P3)	°C	T _L to T _H 0 to +70 − 40 to +85 − 40 to +105	°C
Operating temperature ranges (3.3V±10%) – standard	°C	T _L to T _H 0 to +70	°C
Storage temperature range	T _{stg}	− 65 to +150	°C
Current drain per pin ⁽²⁾ – excluding VDD and VSS	I _D	25	mA

(1) All voltages are with respect to V_{SS}.
(2) Maximum current drain per pin is for one pin at a time, limited by an external resistor.

Note: This device contains circuitry designed to protect against damage due to high electrostatic voltages or electric fields. However, it is recommended that normal precautions be taken to avoid the application of any voltages higher than those given in the maximum ratings table to this high impedance circuit. For maximum reliability all unused inputs should be tied to either V_{SS} or V_{DD}.

9.2 Thermal characteristics and power considerations

Table 9-2 Package thermal characteristics

Characteristics	Symbol	Value	Unit
Thermal resistance:	θ_{JA}		
– Plastic 28-pin SOIC package		60	°C/W
– Plastic 28-pin PDIP package		60	

The average chip junction temperature, T_J , in degrees Celsius can be obtained from the following equation:

$$T_J = T_A + (P_D \cdot \theta_{JA})$$
 [1]

where:

- T_A = Ambient temperature (°C)
- θ_{JA} = Package thermal resistance, junction-to-ambient (°C/W)
- $P_D = P_{INT} + P_{I/O}$ (W)
- P_{INT} = Internal chip power = $I_{DD} \cdot V_{DD}$ (W)
- $P_{I/O}$ = Power dissipation on input and output pins (user determined)

An approximate relationship between P_D and T_J (if $P_{I/O}$ is neglected) is:

9

$$P_D = \frac{K}{T_J + 273}$$
 [2]

Solving equations [1] and [2] for K gives:

$$K = P_D \cdot (T_A + 273) + \theta_{JA} \cdot P_D^2$$
 [3]

where K is a constant for a particular part. K can be determined by measuring P_D (at equilibrium) for a known T_A . Using this value of K, the values of P_D and T_J can be obtained for any value of T_A by solving the above equations. The package thermal characteristics are shown in Table 9-2.

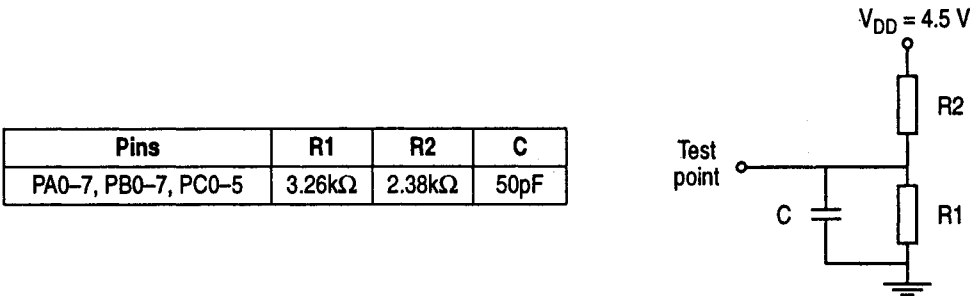


Figure 9-1 Equivalent test load

9.3 DC electrical characteristics

Table 9-3 DC electrical characteristics (V_{DD} = 5 V)

(V_{DD} = 5.0 V_{DC} ± 10%, V_{SS} = 0 V_{DC}, T_A = T_L to T_H)

Characteristic	Symbol	Min.	Typ. ⁽¹⁾	Max.	Unit
Output voltage					
I _{LOAD} = −10 μA	V _{OH}	V _{DD} − 0.1	—	—	V
I _{LOAD} = +10 μA	V _{OL}	→	—	0.1	V
Output high voltage (I _{LOAD} = −0.8 mA) Ports (PA0–7, PB0–7, PC0–5)	V _{OH}	V _{DD} − 0.8	—	—	V
Output low voltage (I _{LOAD} = +1.6 mA) Ports	V _{OL}	—	—	0.4	V
Input high voltage Ports, OSC1, $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$	V _{IH}	0.7V _{DD}	—	—	V
Input low voltage Ports, OSC1, $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$	V _{IL}	—	—	0.2V _{DD}	V
Data retention mode	V _{RM}	2.0	—	—	V
Supply current ⁽²⁾	I _{DD}				
RUN		—	3.5	6.0	mA
WAIT		—	1.6	3.0	mA
STOP: 0 to 70°C		—	2	50.0	μA
STOP: − 40 to +85°C		—	5	50.0	μA
Input leakage current PA0–7, PB0–7, OSC1, $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$	I _{IN}	—	0.2	1.0	μA
Capacitance Ports (as input or output)	C _{OUT} C _{IN}	— —	— —	12 8	pF pF
Port C pull-up resistance (MC68HC05P3 only)	R _{PORTC}	700	—	950	kΩ
Pull-up source current (V _{IN} = 0.2 V _{DD}) (MC68HC705P3 only) PC0–7	I _{PU}	—	75	—	A
MC68HC705P3 EPROM					
Programming voltage	V _{PP}	—	18.5	TBD	V
Programming current	I _{PP}	TBD	TBD	TBD	mA
Programming time	t _{PROG}	4	—	—	ms

- (1) Typical values are at mid point of voltage range and at 25°C only.
- (2) All I_{DD} measurements taken with suitable decoupling capacitors across the power supply to suppress the transient switching currents inherent in CMOS designs (see Section 2.4.1). RUN and WAIT I_{DD}: measured using an external square-wave clock source (f_{OP} = 2.1 MHz); all inputs 0.2V from rail; no DC loads; maximum load on outputs 50 pF (20 pF on OSC2). WAIT I_{DD}: only the timer system active; current varies linearly with the OSC2 capacitance. STOP and WAIT I_{DD}: all ports configured as inputs, PC0 – PC5 connected to V_{DD}; V_{IL} = 0.2V and V_{IH} = V_{DD} − 0.2V. STOP I_{DD}: measured with OSC1 = V_{SS}.

Warning: EPROM programming should be carried out at room temperature only.

Table 9-4 DC electrical characteristics (V_{DD} = 3.3V)

(V_{DD} = 3.3 V_{DC} ± 10%, V_{SS} = 0 V_{DC}, T_A = 0 to 70°C)

Characteristics	Symbol	Min.	Typ. ⁽¹⁾	Max.	Unit
Output voltage					
I _{LOAD} = -10 μA	V _{OH}	V _{DD} - 0.1	—	—	V
I _{LOAD} = +10 μA	V _{OL}	—	—	0.1	V
Output high voltage (I _{LOAD} = -0.4 mA) Ports (PA0-7, PB0-7, PC0-5)	V _{OH}	V _{DD} - 0.8	—	—	V
Output low voltage (I _{LOAD} = +0.8 mA) Ports	V _{OL}	—	—	0.4	V
Input high voltage Ports, OSC1, $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$	V _{IH}	0.7V _{DD}	—	—	V
Input low voltage Ports, OSC1, $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$	V _{IL}	—	—	0.2V _{DD}	V
Data retention mode	V _{RM}	2.0	—	—	V
Supply current ⁽²⁾ : f _{OP} = 1.05 MHz	I _{DD}				
RUN		—	0.75	3.0	mA
WAIT		—	0.25	1.5	mA
STOP		—	1.5	25.0	μA
Input leakage current PA0-7, PB0-7, OSC1, $\overline{\text{IRQ}}$, $\overline{\text{RESET}}$	I _{IN}	—	200	1000	nA
Capacitance Ports (as input or output)	C _{OUT} C _{IN}	— —	— —	12 8	pF pF
Port C pull-up resistance (MC68HC05P3 only)	R _{PORTC}	700	—	950	kΩ
Pull-up source current (V _{IN} = 0.2 V _{DD}) (MC68HC705P3 only) PC0-7	I _{PU}	—	30	—	A

(1) Typical values are at mid point of voltage range and at 25°C only.

(2) All I_{DD} measurements taken with suitable decoupling capacitors across the power supply to suppress the transient switching currents inherent in CMOS designs (see Section 2.4.1). RUN and WAIT I_{DD}: measured using an external square-wave clock source (f_{OP} = 1.0 MHz); all inputs 0.2V from rail; no DC loads; maximum load on outputs 50pF (20pF on OSC2). WAIT I_{DD}: only the timer system active; current varies linearly with the OSC2 capacitance. STOP and WAIT I_{DD}: all ports configured as inputs, PC0 – PC5 connected to V_{DD}; V_{IL} = 0.2V and V_{IH} = V_{DD} - 0.2V. STOP I_{DD}: measured with OSC1 = V_{SS}.

9.4 AC electrical characteristics

Table 9-5 AC electrical characteristics (V_{DD} = 5V)

(V_{DD} = 5.0 V_{DC} ±10%, V_{SS} = 0 V_{DC}, T_A = T_L to T_H)

Characteristic	Symbol	Min.	Max.	Unit
Frequency of operation:				
Oscillator frequency	f _{OSC}	0	4.2	MHz
MCU bus frequency	f _{OP}	0	2.1	
Processor cycle time	t _{CYC}	480	—	ns
Oscillator clock pulse width	t _{OH} , t _{OL}	90	—	ns
RESET pulse width	t _{RL}	1.5	—	t _{CYC}
Power-on reset delay	t _{PORL}	4064	4064	t _{CYC}
Crystal oscillator start-up time	t _{OXOV}	—	100	ms
Oscillator stabilization time	t _{RCON}	—	50	μs
EEPROM byte programming time	t _{EPGM}	—	15	ms
EEPROM byte erase time	t _{EBYTE}	—	15	ms
EEPROM block erase time	t _{EBLOCK}	—	60	ms
EEPROM bulk erase time	t _{EBULK}	—	200	ms
EEPROM programming voltage fall time	t _{FPV}	—	10	μs

Table 9-6 AC electrical characteristics (V_{DD} = 3.3V)

(V_{DD} = 3.3 V_{DC} ± 10%, V_{SS} = 0 V_{DC}, T_A = 0 to 70°C)

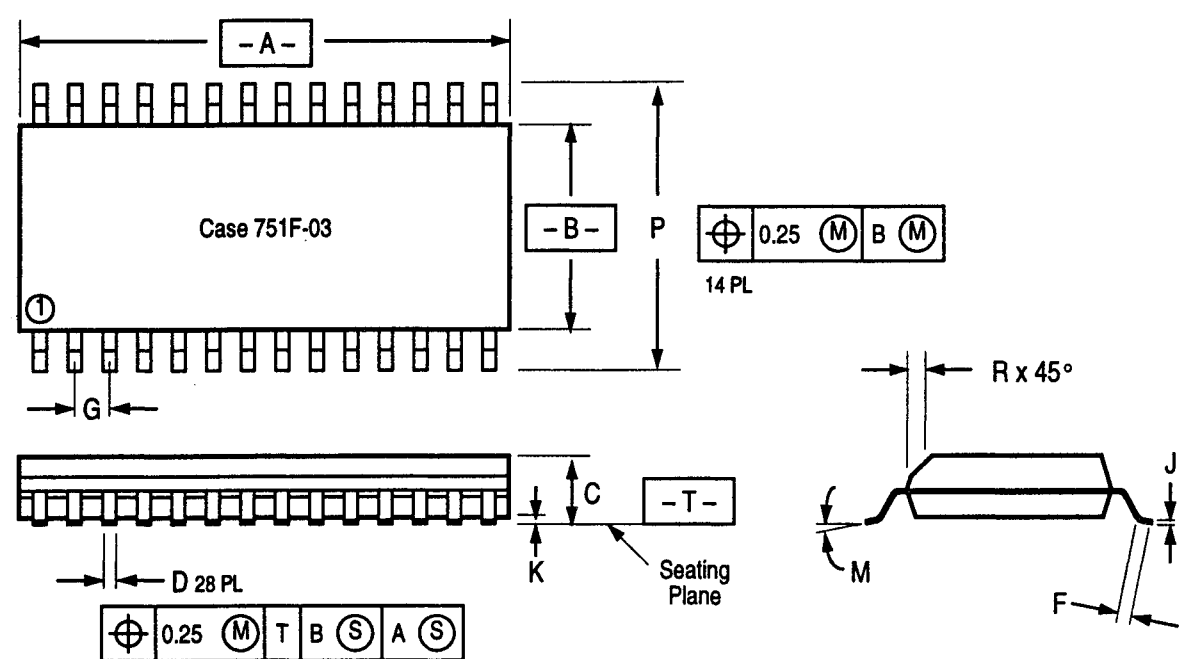
Characteristic	Symbol	Min.	Max.	Unit
Frequency of operation:				
Oscillator frequency	f _{OSC}	0	2.0	MHz
MCU Bus frequency	f _{OP}	0	1.0	
Processor cycle time	t _{CYC}	100	—	ns
Oscillator clock pulse width	t _{OH} , t _{OL}	90	—	ns
RESET pulse width	t _{RL}	1.5	—	t _{CYC}
Power-on reset delay	t _{PORL}	4064	4064	t _{CYC}
Crystal oscillator start-up time	t _{OXOV}	—	100	ms
Oscillator stabilization time	t _{RCON}	—	50	μs
EEPROM byte programming time	t _{EPGM}	—	15	ms
EEPROM byte erase time	t _{EBYTE}	—	15	ms
EEPROM block erase time	t _{EBLOCK}	—	60	ms
EEPROM bulk erase time	t _{EBULK}	—	200	ms
EEPROM programming voltage fall time	t _{FPV}	—	10	μs

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MECHANICAL DATA

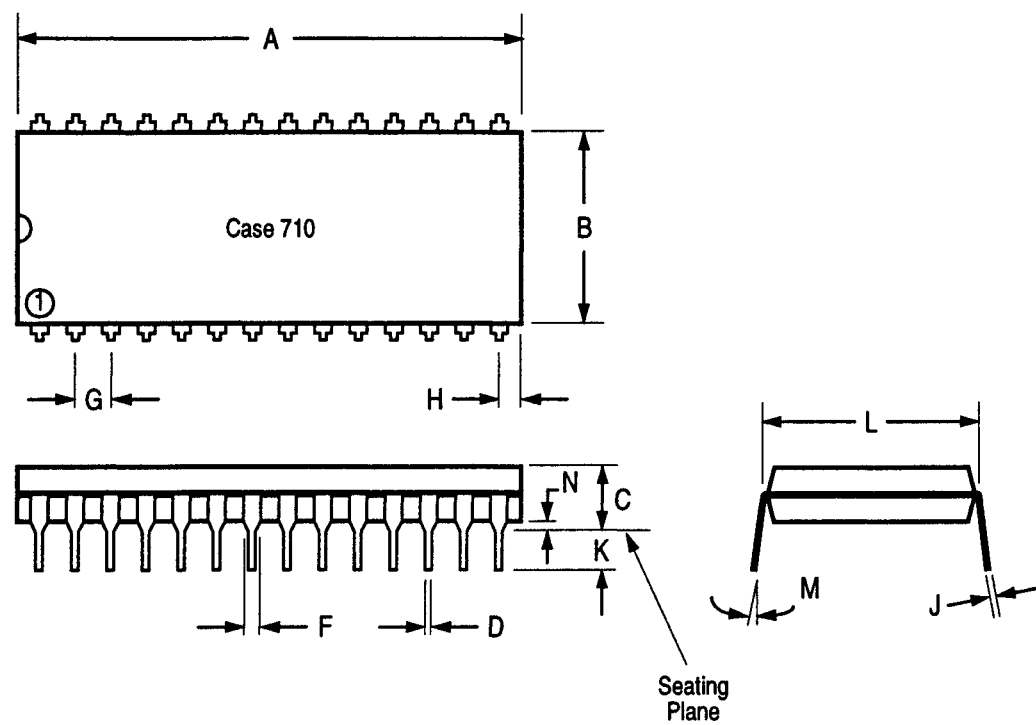
10.1 28-pin SOIC package



Dim.	Min.	Max.	Notes	Dim.	Min.	Max.
A	17.80	18.05	1. Dimensions 'A' and 'B' are datums and 'T' is a datum surface. 2. Dimensioning and tolerancing per ANSI Y14.5M, 1982. 3. All dimensions in mm. 4. Dimensions 'A' and 'B' do not include mould protrusion. 5. Maximum mould protrusion is 0.15 mm per side.	J	0.229	0.317
B	7.40	7.60		K	0.127	0.292
C	2.35	2.65		M	0°	8°
D	0.35	0.49		P	10.05	10.55
F	0.41	0.90		R	0.25	0.75
G	1.27 BSC			—	—	—

Figure 10-1 Mechanical dimensions for 28-pin SOIC package

10.2 28-pin PDIP package



Dim.	Min.	Max.	Notes	Dim.	Min.	Max.
A	36.45	37.21	1. All dimensions in mm. 2. Positional tolerance of leads ('D') shall be within 0.25 mm at maximum material condition, in relation to seating plane and to each other. 3. Dimension 'L' is to centre of leads when formed parallel. 4. Dimension 'B' does not include mould protrusion.	H	1.65	2.16
B	13.72	14.22		J	0.20	0.38
C	3.94	5.08		K	2.92	3.43
D	0.36	0.56		L	15.24 BSC	
F	1.02	1.52		M	0°	15°
G	2.54 BSC			N	0.51	1.02

Figure 10-2 Mechanical dimensions for 28-pin PDIP package

11

ORDERING INFORMATION

This section describes the information needed to order the MC68HC05P3 or MC68HC705P3.

Table 11-1 MC order numbers

Device title	Package type	Temperature	Part number
MC68HC05P3	28-pin SOIC	0 to +70°C	MC68HC05P3DW
		-40 to +85°C	MC68HC05P3CDW
		-40 to +105°C	MC68HC05P3VDW
	28-pin PDIP	0 to +70°C	MC68HC05P3P
		-40 to +85°C	MC68HC05P3CP
		-40 to +105°C	MC68HC05P3VP
MC68HC705P3	28-pin SOIC	0 to +70°C	MC68HC705P3S
		-40 to +85°C	MC68HC705P3CS

Warning: 3.3V specification relates to 0 to 70°C temperature range only.

To initiate a ROM pattern for the MC68HC05P3, it is necessary to first contact your local field service office, local sales person or Motorola representative. Please note that you will need to supply details such as: mask option selections; temperature range; oscillator frequency; package type; electrical test requirements; and device marking details so that an order can be processed, and a customer specific part number allocated. Refer to Table 11-1 for appropriate part numbers.

11

11.1 EPROM

An 8K byte EPROM programmed with the customer's software (positive logic for address and data) should be submitted for pattern generation. As the MC68HC05P3 has only a 4K byte memory map, only the lower half of the EPROM (\$0000 to \$0FFF) should be used. All unused bytes should be programmed to \$00.

The EPROM should be clearly labelled, placed in a conductive IC carrier and securely packed.

11.2 Verification media

All original pattern media (EPROMs) are filed for contractual purposes and are not returned. A computer listing of the ROM code will be generated and returned with a listing verification form. The listing should be thoroughly checked and the verification form completed, signed and returned to Motorola. The signed verification form constitutes the contractual agreement for creation of the custom mask. If desired, Motorola will program blank EPROMs (supplied by the customer) from the data file used to create the custom mask, to aid in the verification process.

11.3 ROM verification units (RVU)

Ten MCUs containing the customer's ROM pattern will be provided for program verification. These units will have been made using the custom mask but are for ROM verification only. For expediency, they are usually unmarked and are tested only at room temperature (25°C) and at 5 Volts. These RVUs are included in the mask charge and are not production parts. They are neither backed nor guaranteed by Motorola Quality Assurance.

A

MC68HC05P3 AND MC68HC705P3

DIFFERENCES

The information given in this appendix summarizes the differences between the MC68HC05P3 and the MC68HC705P3. The same information can be found in greater detail in the appropriate sections of the book.

Important: Information given for the MC68HC705P3 cannot be guaranteed. All values are design targets only and may change before the MC68HC705P3 is qualified.

A.1 Mask options

A.1.1 MC68HC05P3

There are two mask options on the MC68HC05P3 which are programmed during manufacture and therefore must be specified on the order form: COP watchdog timer enable/disable and an option to make $\overline{\text{IRQ}}$ either edge sensitive or edge-and-level sensitive.

A.1.2 MC68HC705P3

In the case of the MC68HC705P3, an option register replaces the mask options of the MC68HC05P3. Only two bits of this register are of interest to the user: OPTCOP and OPTIRQ. The remaining bits are reserved.



	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
$\overline{\text{IRQ}}$ /COP status/control (OPT)	\$0F	0	1	0	0	1	0	OPTCOP	OPTIRQ	0100 1000

A.1.2.1 OPTCOP

OPTCOP enables or disables the COP. It is cleared by reset, thus enabling the COP. This bit can be written only once, so that the COP state can not be changed after the first write to this register. It is recommended that the user writes this bit as soon as possible after reset, in order to lock the state of the COP.

OPTCOP — Computer operating properly watchdog enable/disable

1 (set) — COP watchdog disabled.

0 (clear) — COP watchdog enabled.

A.1.2.2 OPTIRQ

Either an edge-and-level sensitive trigger, or an edge sensitive only trigger is selected by modifying bit 0 (OPTIRQ) of register \$0F. At reset this bit is cleared so that \overline{TRQ} is falling-edge sensitive only. The read/write bit must be set by software to get a falling-edge-and-low-level sensitive trigger.

OPTIRQ — Interrupt triggering sensitivity

1 (set) — \overline{TRQ} is falling-edge-and-low-level sensitive.

0 (clear) — \overline{TRQ} is falling-edge sensitive only.

Note: *It is not advisable to change the value of OPTIRQ more than once, since this is not possible with the ROM version.
When changing the value of the OPTIRQ bit, the I-bit in the CCR should be set in order that all interrupts are disabled.*

A.2 Modes of operation

A


A.2.1 MC68HC05P3

The normal operating mode of the MC68HC05P3 is user (or single chip) mode, in which the device functions as a self-contained microcomputer unit, with all on-board peripherals and I/O ports available to the user. All address and data activity occurs within the MCU. There is also a bootloader mode, primarily for factory test purposes. In addition to these modes, there are three low power modes which may be entered and exited at will from user mode: STOP, WAIT and data retention.

A.2.2 MC68HC705P3

The MC68HC705P3 also has two modes of operation: user mode and EPROM bootloader mode. Table A-1 shows the conditions required to enter the EPROM modes of operation on the rising edge of RESET.

Table A-1 MC68HC705P3 operating mode entry conditions

RESET	IRQ/VPP	PC4	PC3	PC2	Mode	
	V _{SS} to V _{DD}	x	x	x	User	
	2V _{DD}	1	0	1	EPROM bootloader	Verify only
		1	1	0		Program 1 byte
		1	1	1		Program 4 bytes

x = don't care

For the MC68HC705P3, all vectors are fetched from EPROM in user mode, therefore, the EPROM must be programmed (via the bootloader mode) before the device is powered up in user mode.

A.2.2.1 EPROM bootloader mode

This mode is used for programming the on-board EPROM. In bootloader mode the operation of the device is the same as in user mode, except that the vectors are fetched from a reserved area of ROM at locations \$0FE0 to \$0FEF, instead of from the EPROM. The pin assignments are identical to those of user mode (see Figure 2-3). Because the addresses in the MC68HC705P3 and the external EPROM containing the user code are incremented independently, it is essential that the data layout in the 27256 EPROM conforms exactly to the MC68HC705P3 memory map.

The bootloader uses two external latches to address the memory device containing the code to be copied. Figure A-1 shows a suggested EPROM programming circuit.

A.2.2.2 Bootloader functions

The bootloader code deals with the copying of user code from an external EPROM into the on-chip EPROM. The bootloader performs a programming pass and then does a verify pass.

Two pins, PC0 and PC1, are used to drive the PROG and VERF LED outputs. While the EPROM is being programmed, the PROG LED lights up; when programming is complete, the internal EPROM contents are compared to that of the external EPROM and, if they match exactly, the VERF LED lights up.

Note: The EPROM must be in the erased state before a program cycle. The erased state of the EPROM is \$00.



A.3.2 MC68HC705P3

The MC68HC705P3 has 224 bytes of bootloader ROM, ranging from \$0F00 to \$0FDF, and bootloader vectors from \$0FE0 to \$0FEF. This program contains code to program the EPROM by copying from a 27256 EPROM master device.

Note: The bootloader ROM is not accessible if the ELATCH bit in the EPROM programming register (\$1D) is set.

The MC68HC705P3 has 3072 bytes of EPROM located from \$0300 to \$0EFF, plus 10 bytes of user vectors from \$0FF6 to \$0FFF. Four bytes of EPROM can be programmed simultaneously by correctly manipulating the bits in the EPROM programming register.

A.3.2.1 EPROM programming register (PROG)

	Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	State on reset
EPROM programming (PROG)	\$001D	0	0	0	0	0	ELATCH	0	EPMG	0000 0000

EPMG — EPROM program control

1 (set) — Programming power connected to the EPROM array.

0 (clear) — Programming power disconnected from the EPROM array.

ELATCH and EPMG cannot be set on the same write operation. EPMG can only be set if ELATCH is set. EPMG is automatically cleared when ELATCH is cleared.

ELATCH — EPROM latch control

1 (set) — EPROM address and data buses configured for programming.

0 (clear) — EPROM address and data buses configured for normal reads

ELATCH causes address and data buses to be latched when a write to EPROM is carried out. The EPROM cannot be read if ELATCH = 1. This bit should not be set unless a programming voltage is applied to the VPP pin.

A

A.3.2.2 EPROM programming instructions

The following procedures should be carried out when programming the EPROM. In order to prevent damage to the device, V_{DD} should always be applied to the part before V_{PP} when powering up the device. Similarly, V_{PP} should be removed from the part before V_{DD} when switching the power off.

- 1) Turn off power to the circuit.
- 2) Install the MCU and the EPROM.
- 3) Select the bootloader function:
Program 1 byte: Open S1 and S2 and close S3.
Program 4 bytes: Open S1, S2 and S3.
Verify only: Open S1 and S3 and close S2.
- 4) Close switch S4 to hold the MCU in reset.
- 5) Apply V_{DD} to the circuit.
- 6) Apply the EPROM programming voltage (V_{PP}) to the circuit.
- 7) Open switch S4 to take the MCU out of reset.
During programming the PROG LED turns on and is switched off when the verification routine begins. If verification is successful, the VERF LED turns on. If the bootloader finds an error during verification, it puts the error address on the external address bus and stops running.
- 8) Close switch S4 to hold the MCU in reset.
- 9) Remove the V_{PP} voltage.
- 10) Remove the V_{DD} voltage.

If the address bits A15–A2 do not change, i.e. all bytes are located within the same four byte address block, then multibyte programming is permitted. The multibyte programming facility allows four bytes of data to be written to the desired addresses after the ELATCH bit has been set (see Table A-1 for multibyte programming entry conditions). The erased state of the EPROM is \$00.

A.4 \overline{IRQ} /VPP pin

A

This is an input-only pin for external interrupt sources. A mask option selects interrupt triggering to be either falling-edge sensitive or falling-edge-and-low-level sensitive. For the MC68HC705P3, this pin also serves as the input for the EPROM programming voltage (V_{PP}).

A.5 Packaging

The MC68HC05P3 is available in 28-pin SOIC and 28-pin PDIP packages. The MC68HC705P3 is available in a one-time programmable 28-pin ceramic DIL package. (See Section 10).

GLOSSARY

This section contains abbreviations and specialist words used in this data sheet and throughout the industry. Further information on many of the terms may be gleaned from Motorola's *M68HC11 Reference Manual*, *M68HC11RM/AD*, or from a variety of standard electronics text books.

\$xxxx	The digits following the '\$' are in hexadecimal format.
%xxxx	The digits following the '%' are in binary format.
A/D, ADC	Analog-to-digital (converter).
Bootstrap mode	In this mode the device automatically loads its internal memory from an external source on reset and then allows this program to be executed.
Byte	Eight bits.
CCR	Condition codes register; an integral part of the CPU.
CERQUAD	A ceramic package type, principally used for EPROM and high temperature devices.
Clear	'0' — the logic zero state; the opposite of 'set'.
CMOS	Complementary metal oxide semiconductor. A semiconductor technology chosen for its low power consumption and good noise immunity.
COP	Computer operating properly. <i>aka</i> 'watchdog'. This circuit is used to detect device runaway and provide a means for restoring correct operation.
CPU	Central processing unit.
D/A, DAC	Digital-to-analog (converter).
EEPROM	Electrically erasable programmable read only memory. <i>aka</i> 'EEROM'.
EPROM	Erasable programmable read only memory. This type of memory requires exposure to ultra-violet wavelengths in order to erase previous data. <i>aka</i> 'PROM'.
ESD	Electrostatic discharge.
Expanded mode	In this mode the internal address and data bus lines are connected to external pins. This enables the device to be used in much more complex systems, where there is a need for external memory for example.

EVS	Evaluation system. One of the range of platforms provided by Motorola for evaluation and emulation of their devices.
HCMOS	High-density complementary metal oxide semiconductor. A semiconductor technology chosen for its low power consumption and good noise immunity.
I/O	Input/output; used to describe a bidirectional pin or function.
Input capture	(IC) This is a function provided by the timing system, whereby an external event is 'captured' by storing the value of a counter at the instant the event is detected.
Interrupt	This refers to an asynchronous external event and the handling of it by the MCU. The external event is detected by the MCU and causes a predetermined action to occur.
$\overline{\text{IRQ}}$	Interrupt request. The overline indicates that this is an active-low signal format.
K byte	A kilo-byte (of memory); 1024 bytes.
LCD	Liquid crystal display.
LSB	Least significant byte.
M68HC05	Motorola's family of 8-bit MCUs.
MCU	Microcontroller unit.
MI BUS	Motorola interconnect bus. A single wire, medium speed serial communications protocol.
MSB	Most significant byte.
Nibble	Half a byte; four bits.
NRZ	Non-return to zero.
Opcode	The opcode is a byte which identifies the particular instruction and operating mode to the CPU. See also: prebyte, operand.
Operand	The operand is a byte containing information the CPU needs to execute a particular instruction. There may be from 0 to 3 operands associated with an opcode. See also: opcode, prebyte.
Output compare	(OC) This is a function provided by the timing system, whereby an external event is generated when an internal counter value matches a predefined value.
PLCC	Plastic leaded chip carrier package.
PLL	Phase-locked loop circuit. This provides a method of frequency multiplication, to enable the use of a low frequency crystal in a high frequency circuit.
Prebyte	This byte is sometimes required to qualify an opcode, in order to fully specify a particular instruction. See also: opcode, operand.

Pull-down, pull-up	These terms refer to resistors, sometimes internal to the device, which are permanently connected to either ground or V_{DD} .
PWM	Pulse width modulation. This term is used to describe a technique where the width of the high and low periods of a waveform is varied, usually to enable a representation of an analog value.
QFP	Quad flat pack package.
RAM	Random access memory. Fast read and write, but contents are lost when the power is removed.
RFI	Radio frequency interference.
RTI	Real-time interrupt.
ROM	Read-only memory. This type of memory is programmed during device manufacture and cannot subsequently be altered.
RS-232C	A standard serial communications protocol.
SAR	Successive approximation register.
SCI	Serial communications interface.
Set	'1' — the logic one state; the opposite of 'clear'.
Silicon glen	An area in the central belt of Scotland, so called because of the concentration of semiconductor manufacturers and users found there.
Single chip mode	In this mode the device functions as a self contained unit, requiring only I/O devices to complete a system.
SPI	Serial peripheral interface.
Test mode	This mode is intended for factory testing.
TTL	Transistor-transistor logic.
UART	Universal asynchronous receiver transmitter.
VCO	Voltage controlled oscillator.
Watchdog	<i>see</i> 'COP'.
Wired-OR	A means of connecting outputs together such that the resulting composite output state is the logical OR of the state of the individual outputs.
Word	Two bytes; 16 bits.
\overline{XIRQ}	Non-maskable interrupt request. The overline indicates that this has an active-low signal format.

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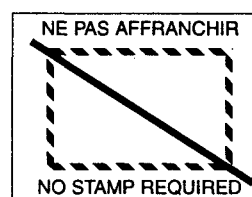


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